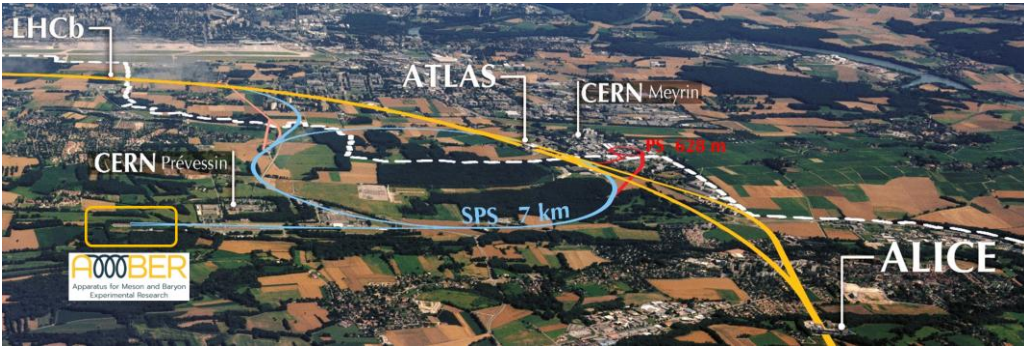
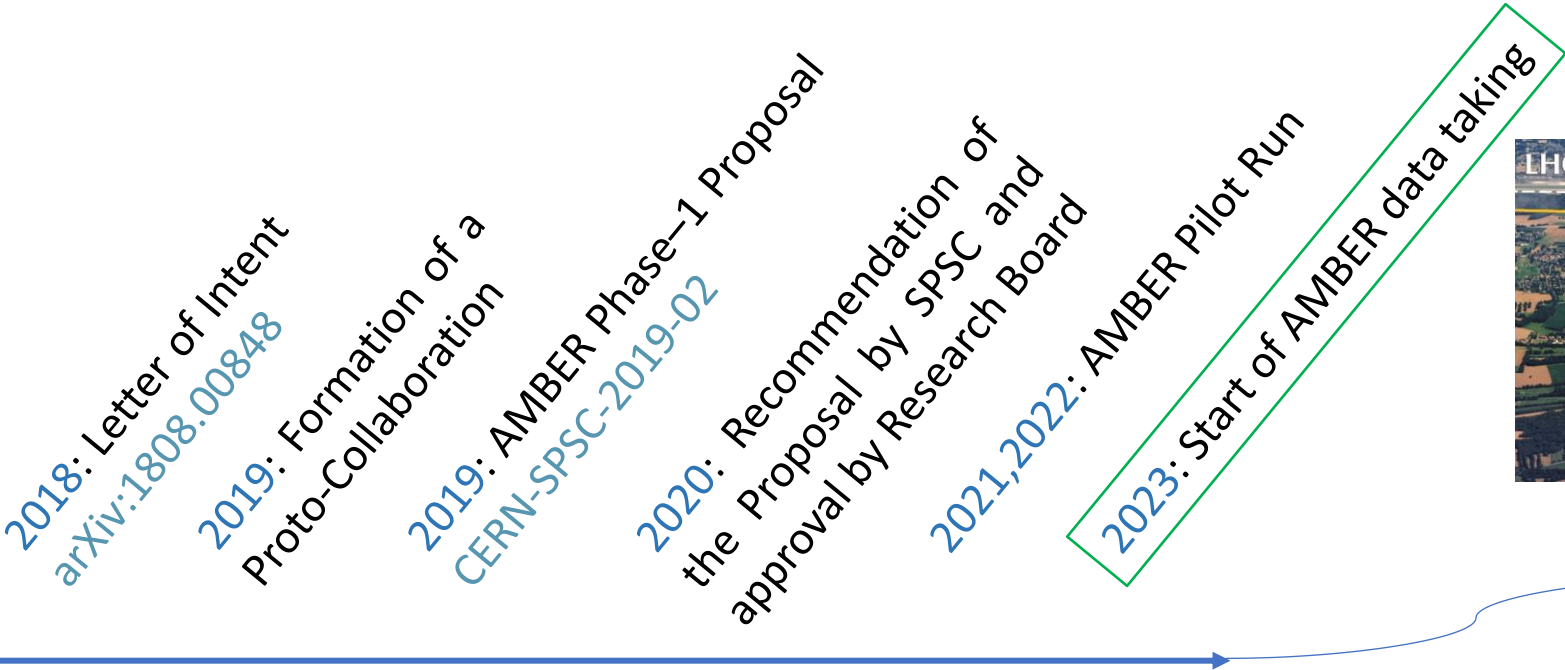


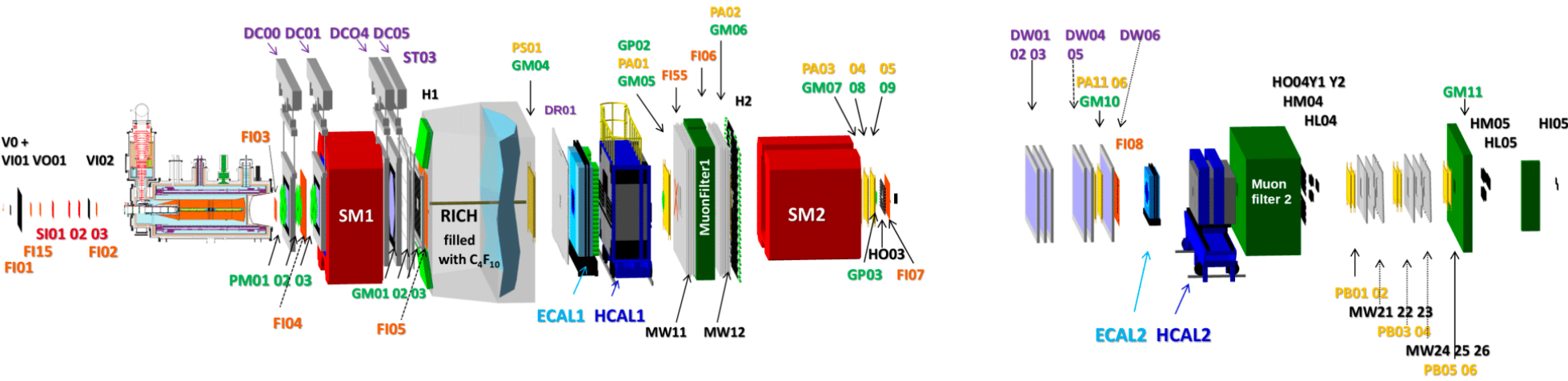
# A new large-area Micromegas detector and its readout electronics for AMBER experiment at CERN

M. Alexeev on behalf of the design working group  
Università di Torino & INFN Torino

# Apparatus for Meson and Baryon Experimental Research (AMBER, NA66)



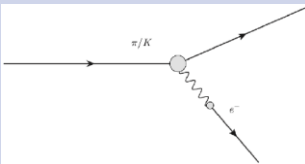
Phase-2 proposal in preparation  
Post LS4 ->



Presently 33 institutes  
from 14 countries, but  
there is no upper limit  
on the values.



# AMBER program

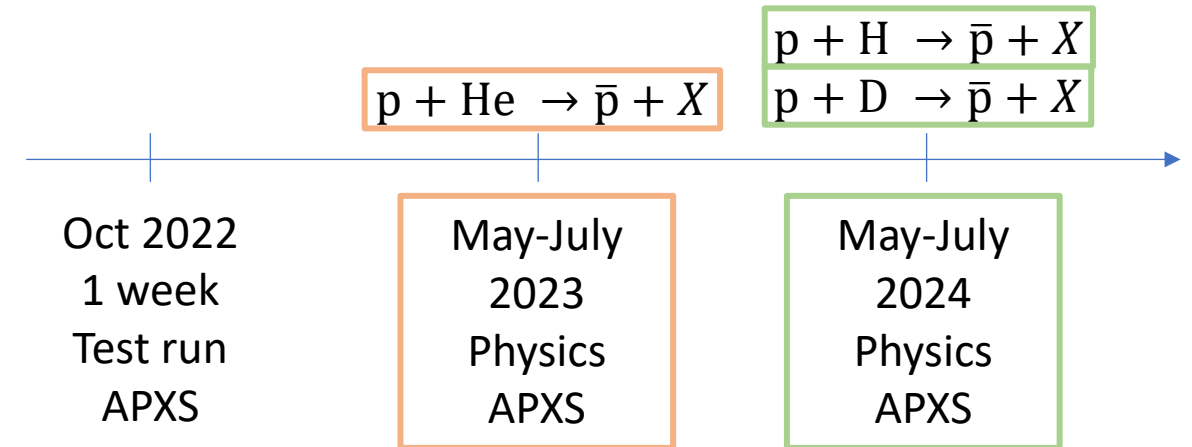
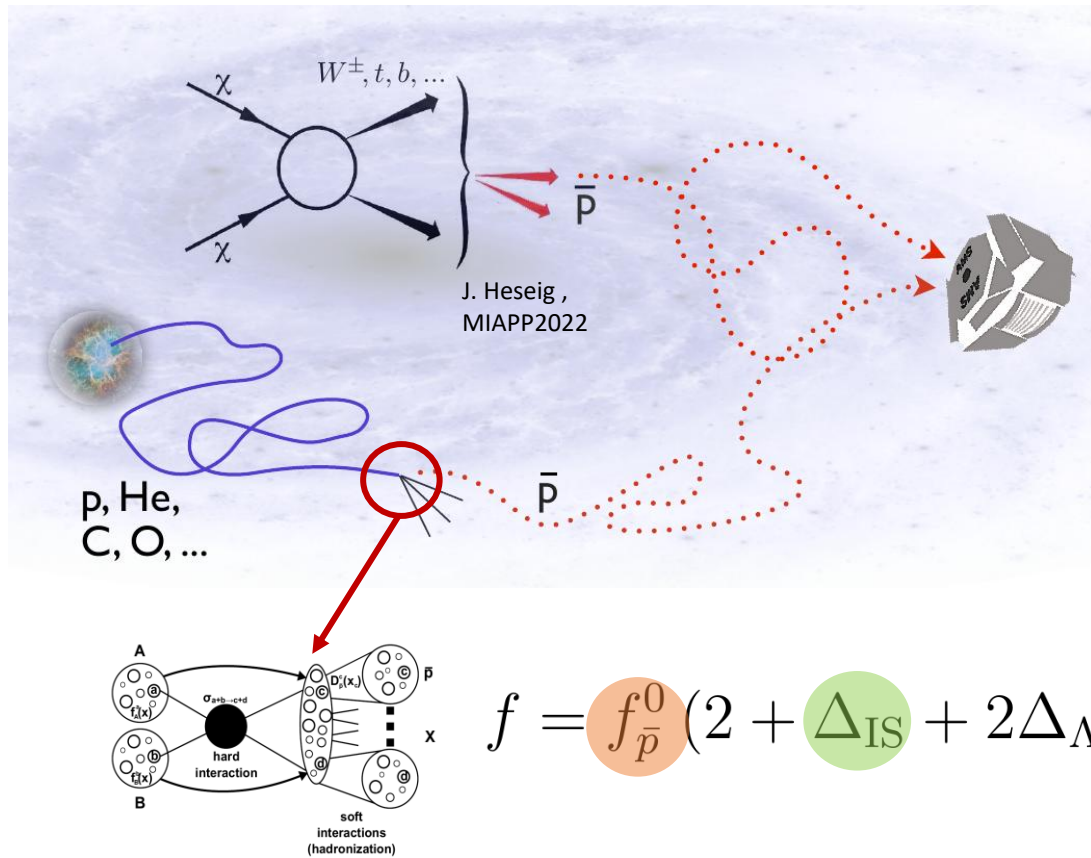
	Beam	Target	Additional hardware
Antiproton production cross section	50 GeV – 280 GeV protons	LH <sub>2</sub> , LHe Done (2023 – 2024)	Liquid He target
Proton radius measurement	100 GeV muons 2025(test) – 2026	High pressure Hydrogen	Active target TPC, tracking stations (SciFi,Silicon)
Drell-Yan measurement with pions	190 GeV charged pions	Carbon, Tungsten	Vertex detector
Drell-Yan measurement with Kaons	~100 GeV charged Kaons	Carbon, Tungsten	Vertex detectors, “active absorber”
Prompt photon measurement	> 100 GeV charged Kaon/pion beams	LH <sub>2</sub> , Nickel	hodoscopes
K-induced spectroscopy	50 GeV – 100 GeV charged Kaons	LH <sub>2</sub>	Recoil ToF forward PID
Meson radii	50 GeV to 280 GeV charged pions and Kaons		

Phase 1  
(approved)  
2023 -> 2032

Phase 2  
(in preparation)  
Beyond LS4

# AMBER APXs (2023-2024)

Antiprotons arise from spallation processes and possible DM decays. Their flux interpretation needs good parametrization of the standard production in the typical occurring reactions.



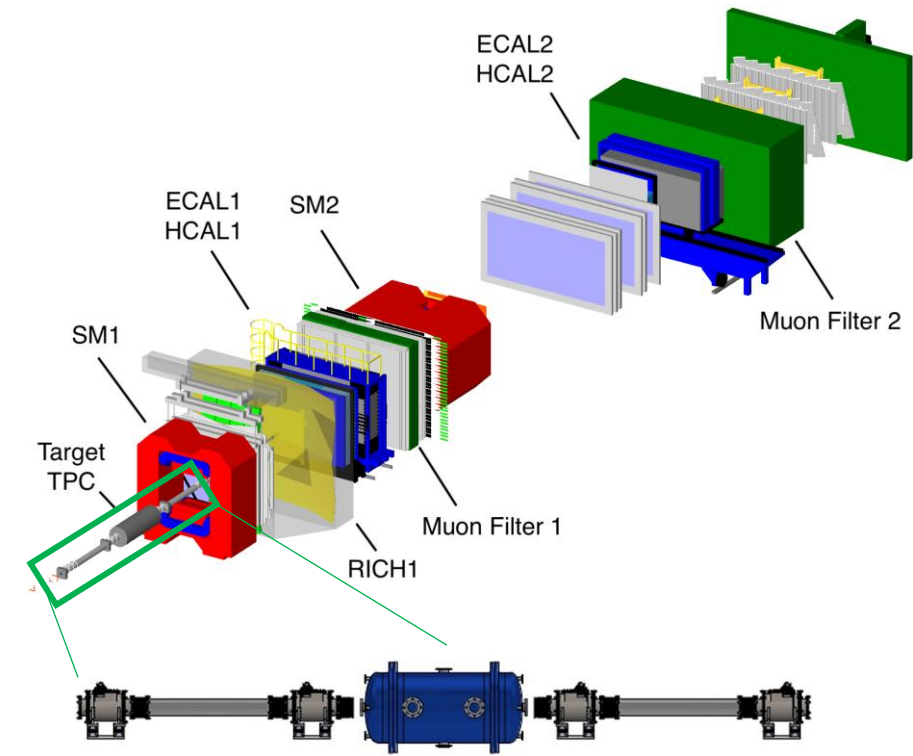
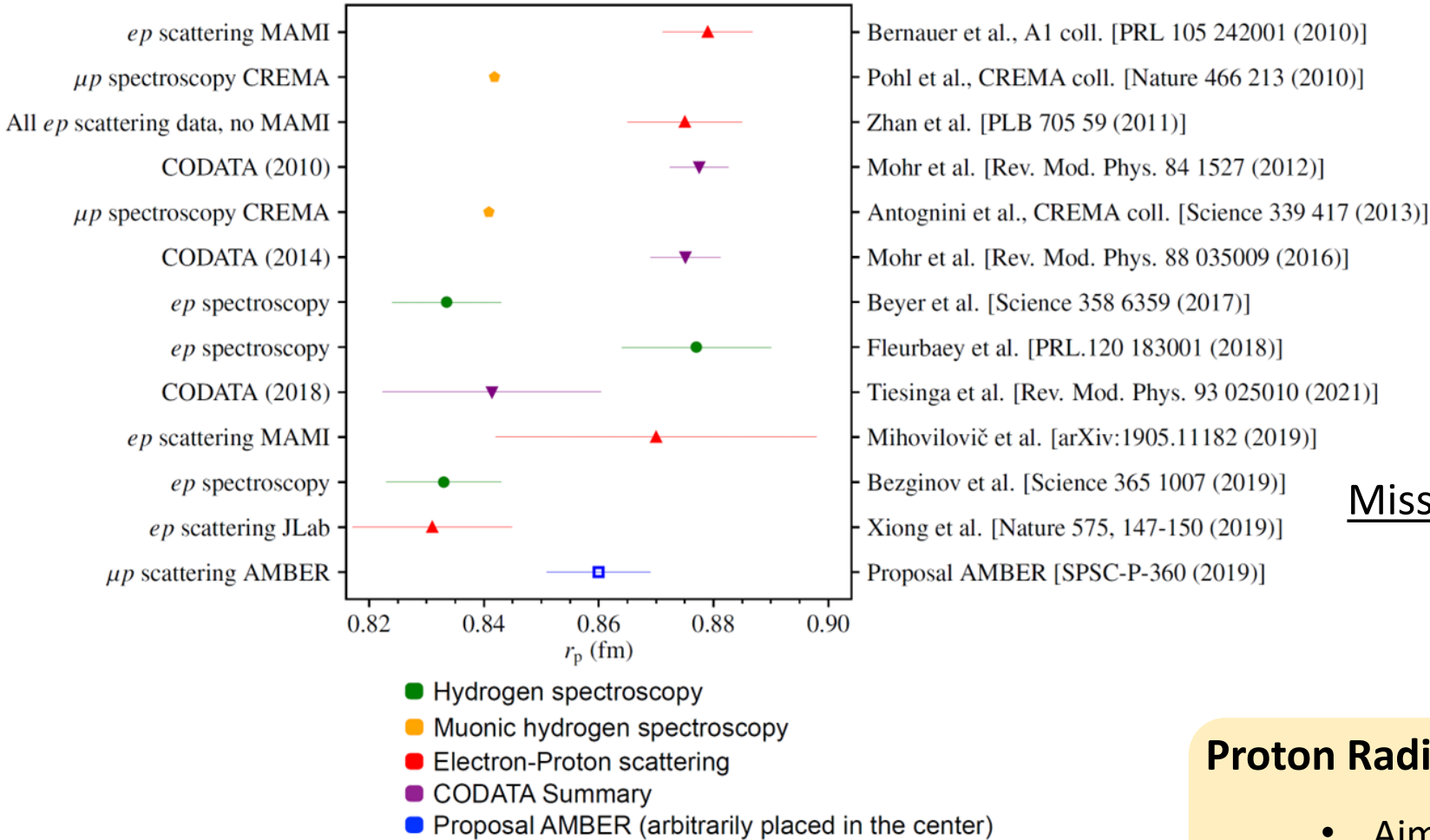
**Minimum bias trigger:** beam trigger with veto on non-scattered beam particle

The major uncertainties in the current antiproton flux interpretation stem from the poor knowledge of the antiproton production from prompt reactions (mainly p+p and p+He) and from antineutron decays.

AMBER collected data at different collision energies ( $\sqrt{s_{NN}} = 10.7 - 21.7$  GeV) to precisely measure p+He, p+H and p+D.

# AMBER PRM (2025/2026)

## Proton-radius puzzle



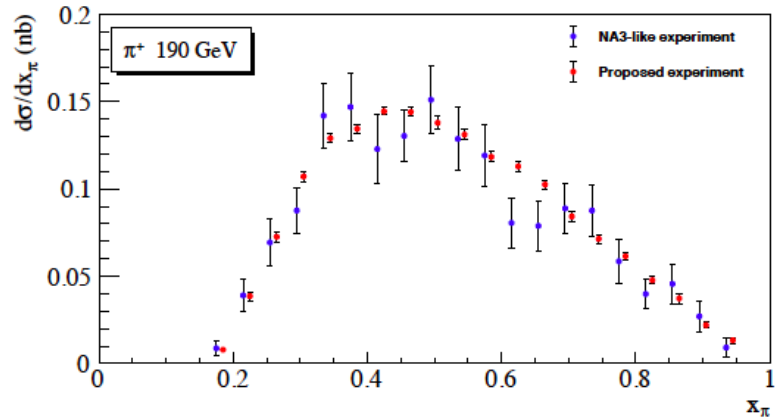
Missing: muon-proton with  $E_\mu$  of 10 - 100 GeV

- Test of lepton universality
- Different systematics compared to others

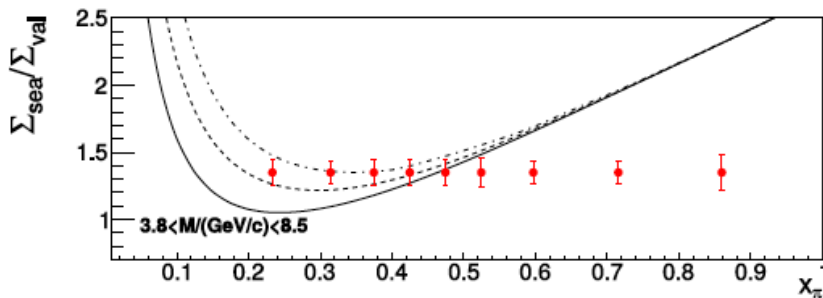
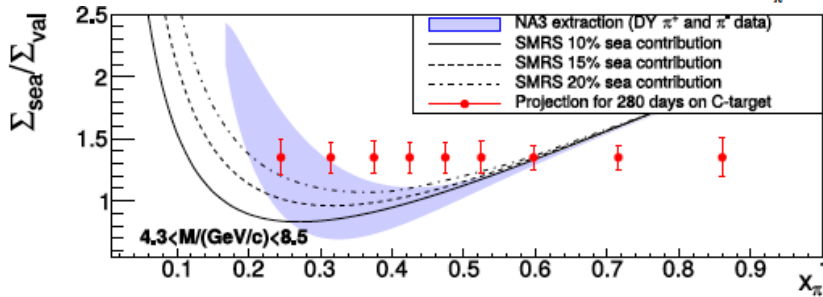
## Proton Radius Measurement @ AMBER

- Aimed precision of charge-radius below 1%
- Aimed  $Q^2$ -range:  $0.001 \text{ GeV}^2/c^2$  to  $0.040 \text{ GeV}^2/c^2$

# AMBER DY (post LS3)



Pion structure in pion induced DY  
Expected accuracy as compared to NA3



Sea quark content of pion can be accurately measured  
at AMBER for the first time

- $\Sigma_V = \sigma^{\pi^-C} - \sigma^{\pi^+C}$ : only valence-valence
- $\Sigma_S = 4\sigma^{\pi^+C} - \sigma^{\pi^-C}$ : no valence-valence
- Collect at least a **factor 10 more statistics** than presently available
- Minimize nuclear effects on target side
  - Projection for  $2 \times 140$  days of Drell-Yan data taking
  - $\pi^+$  to  $\pi^-$  3:1 time sharing
  - 190 GeV beams on Carbon target ( $1.9\lambda_{int}^{\pi}$ )
  - Improvement of shielding to double the intensity is under investigation

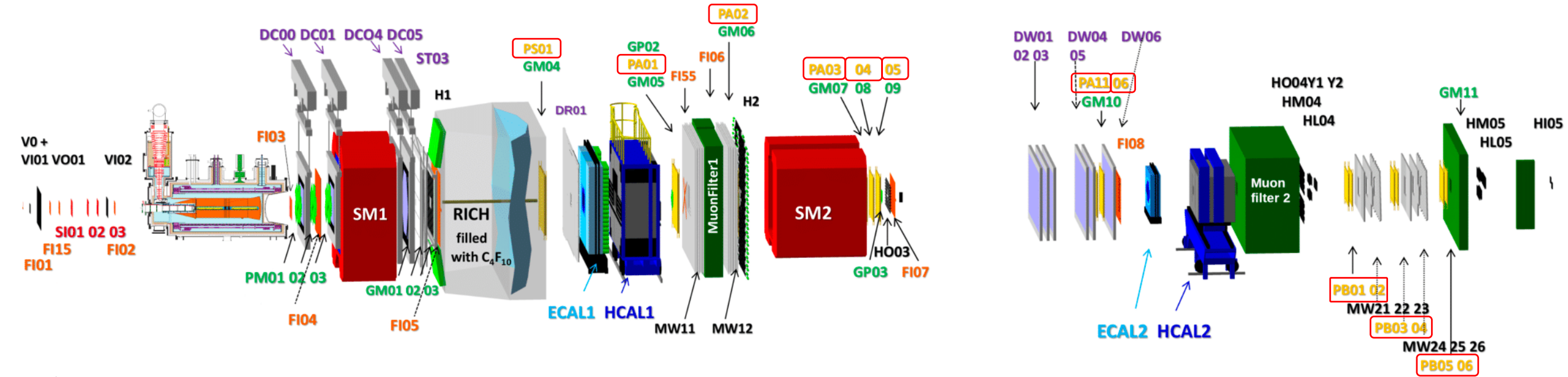
Experiment	Target type	Beam energy (GeV)	Beam type	Beam intensity (part/sec)	DY mass (GeV/c <sup>2</sup> )	DY events
E615	20 cm W	252	$\pi^+$	$17.6 \times 10^7$	4.05 – 8.55	5000
			$\pi^-$	$18.6 \times 10^7$		30000
NA3	30 cm H <sub>2</sub>	200	$\pi^+$	$2.0 \times 10^7$	4.1 – 8.5	40
			$\pi^-$	$3.0 \times 10^7$		121
	6 cm Pt	200	$\pi^+$	$2.0 \times 10^7$	4.2 – 8.5	1767
			$\pi^-$	$3.0 \times 10^7$		4961
NA10	120 cm D <sub>2</sub>	286 140	$\pi^-$	$65 \times 10^7$	4.2 – 8.5 4.35 – 8.5	7800 3200
	12 cm W	286 194 140	$\pi^-$	$65 \times 10^7$	4.2 – 8.5 4.07 – 8.5 4.35 – 8.5	49600 155000 29300
COMPASS 2015	110 cm NH <sub>3</sub>	190	$\pi^-$	$7.0 \times 10^7$	4.3 – 8.5	35000
COMPASS 2018			$\pi^-$			52000
AMBER	75 cm C	190	$\pi^+$	$1.7 \times 10^7$	4.3 – 8.5 4.0 – 8.5	21700 31000
		190	$\pi^-$	$6.8 \times 10^7$	4.3 – 8.5 4.0 – 8.5	67000 91100
	12 cm W	190	$\pi^+$	$0.4 \times 10^7$	4.3 – 8.5 4.0 – 8.5	8300 11700
		190	$\pi^-$	$1.6 \times 10^7$	4.3 – 8.5 4.0 – 8.5	24100 32100

AMBER

Isoscalar target + Both positive and negative beams + High statistics

Probing valence and sea quark contents of pion at AMBER  
Expected statistics 8 to 20 times higher than available

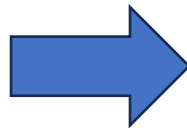
# Why we work on the MM project



❖ In the present AMBER setup one of the main tracker are the MWPC stations

Present situation

- ✓ Triggered DAQ
- ✓ Degraded detectors
- ✓ Limited Team



Reasonable situation

- ❑ Trigger less DAQ
- ❑ Maintenance available for a long period of time
- ❑ Collaboration between, experts, ASIC teams and CERN MPT & GDD workshops



# Decided path to the future

Till 2024



COMPASS MWPCs  
possible path to  
the future

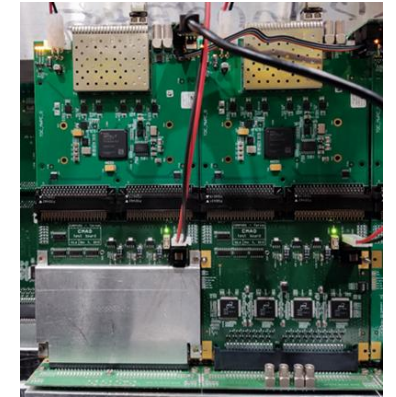


After 2024



Existing detectors

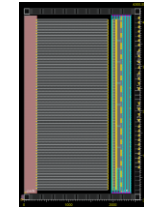
Trigger less  
DAQ (2025)



FPGA based

New FE

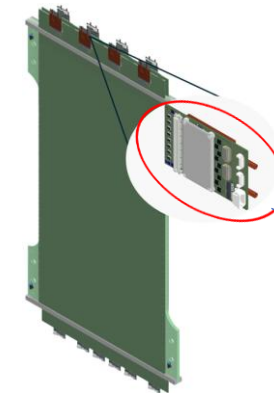
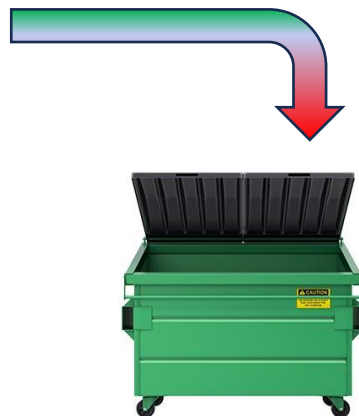
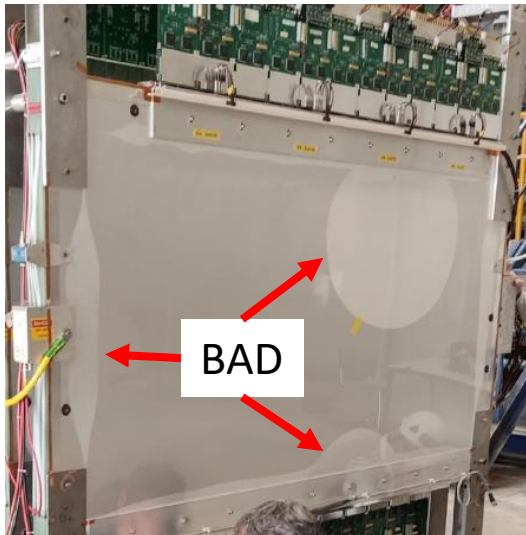
New ASIC



New ASIC

New FE

The 2 developments  
could go together -> **ToRA**



New detectors



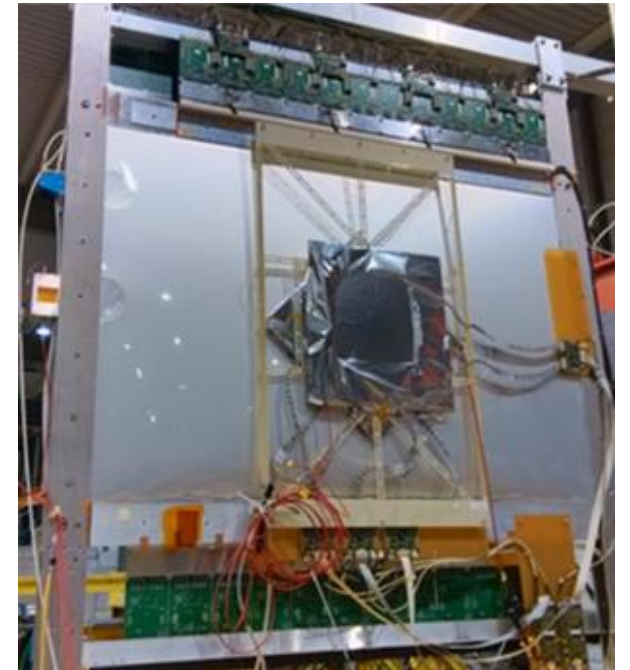
# Base requirements for MWPCs replacement

Characteristics of the COMPASS MWPC detectors

	A-type	A*-type	B-type
# of chambers	7	1	6
Active area (cm <sup>2</sup> )	178 × 120	178 × 120	178 × 90
# of layers/chamber	3	4	2
Planes	$X, U, V$	$X, U, V, Y$	$X, U/V$
Dead zone $\varnothing$ (cm)	16–20	16	22
Wire pitch (mm)	2	2	2
Anode/cathode gap (mm)	8	8	8
# of wires/plane	752	752 ( $X, U, V$ ), 512 ( $Y$ )	752

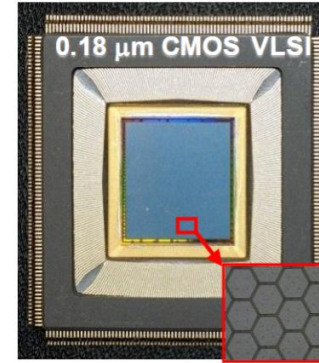
- To reasonably match the existing MWPCs
- To see if we can be better at low cost

MPGD to substitute it?



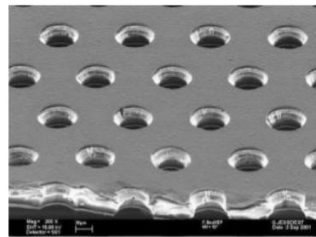
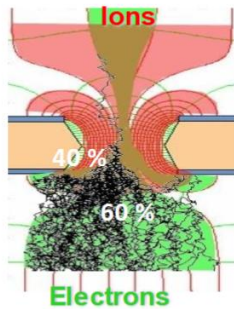
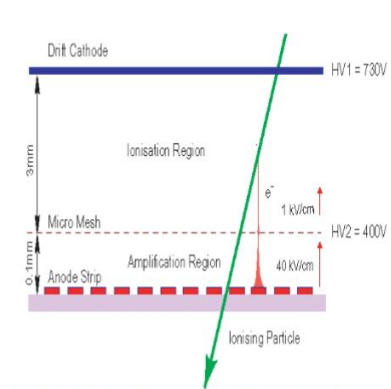
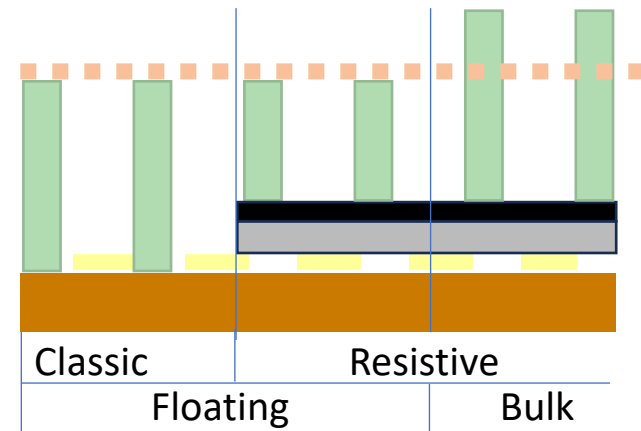
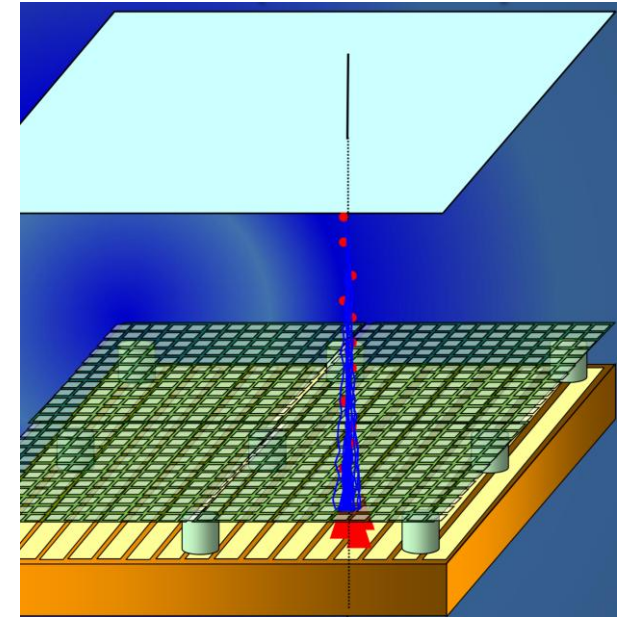
# Micro Pattern Gaseous Detectors

- MSGC
- Micromegas
- GEM
- Thick-GEM, Hole-Type Detectors and RETGEM
- MPDG with CMOS pixel ASICs
- Ingrid Technology

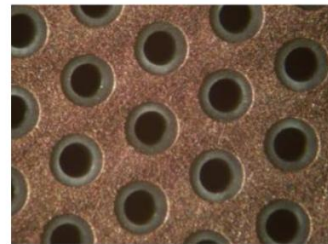
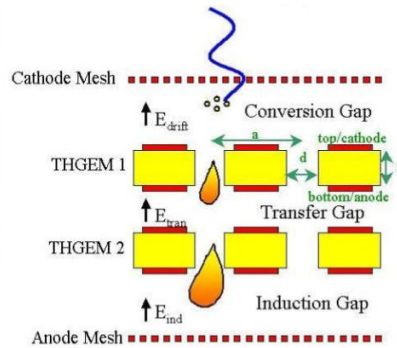


CMOS high density readout electronics

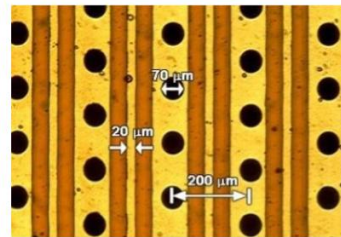
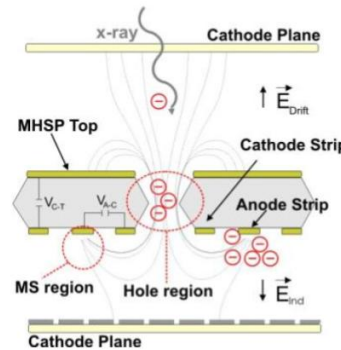
## Micro Mesh Gaseous Structure aka Micromegas aka MM



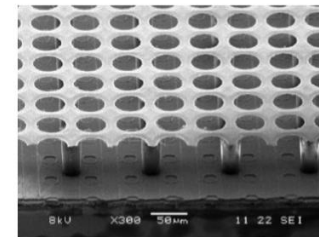
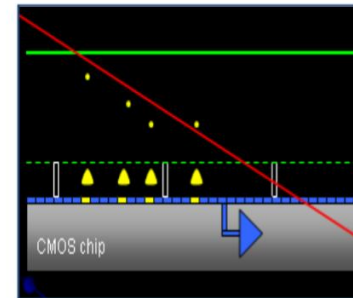
GEM



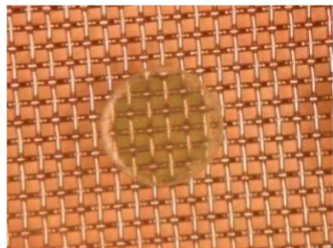
THGEM



MHSP



Ingrid

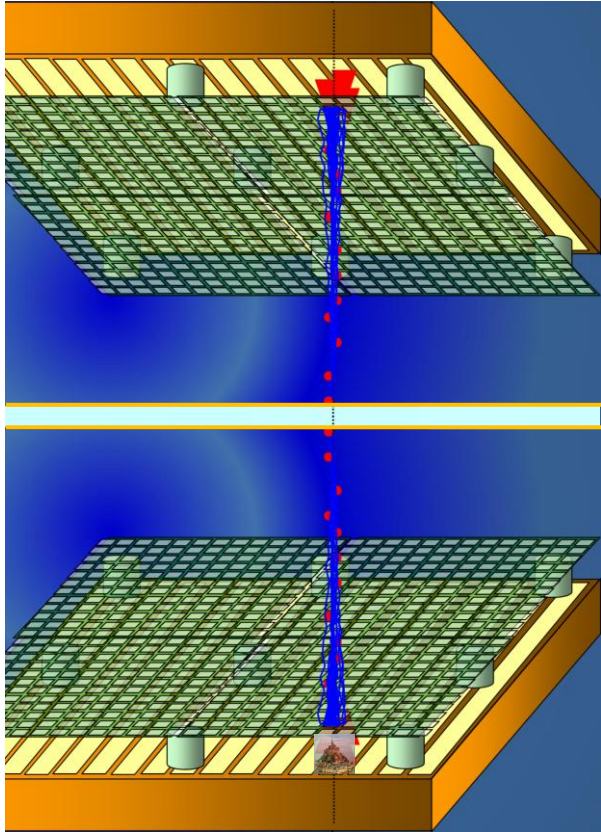


Micromegas

# Concept design (1)

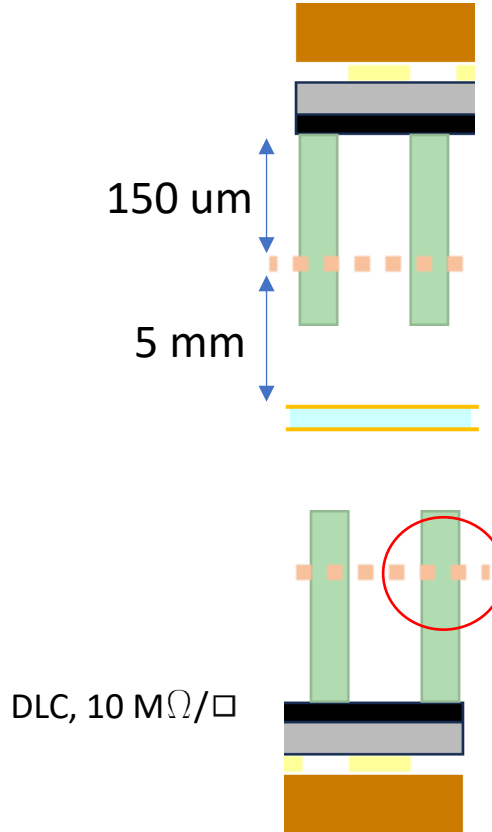
Reduce the material budget?

✓ Common cathode configuration



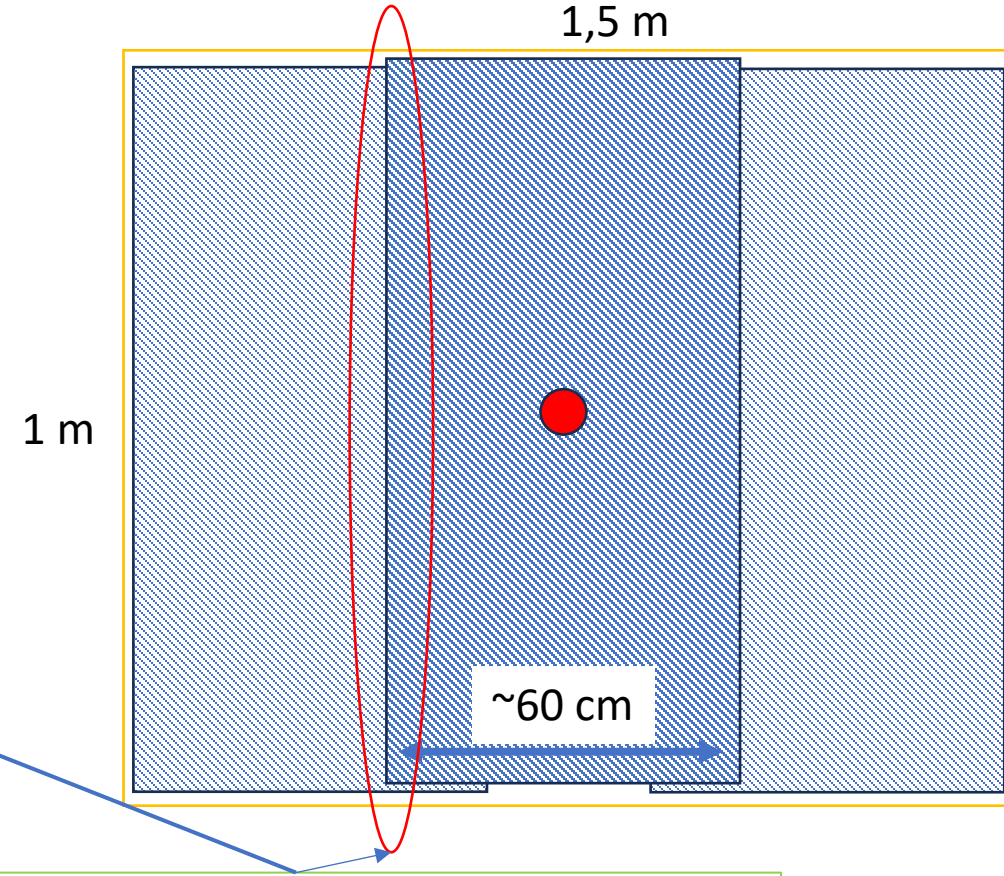
Spark reduction?

✓ Resistive configuration



Technology limitation?

✓ Staggered detector configuration

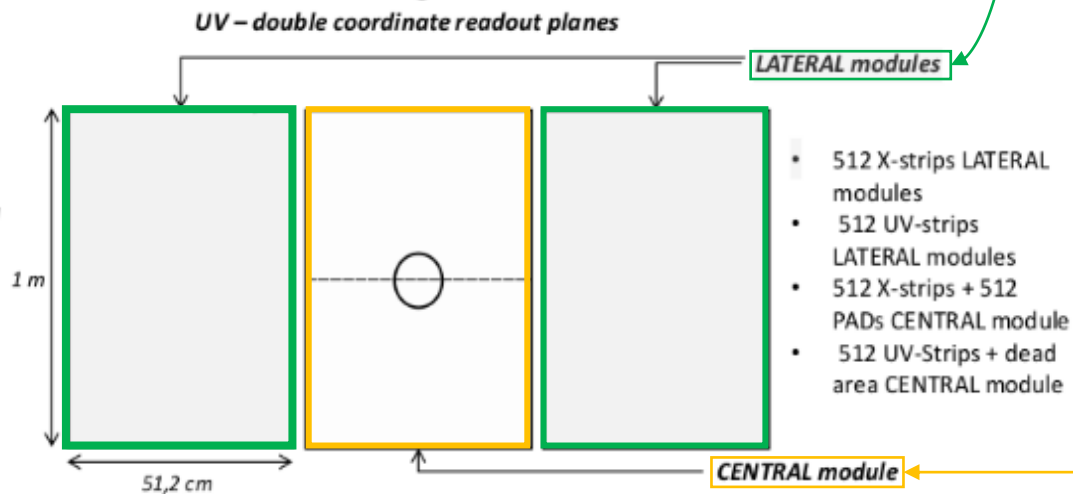
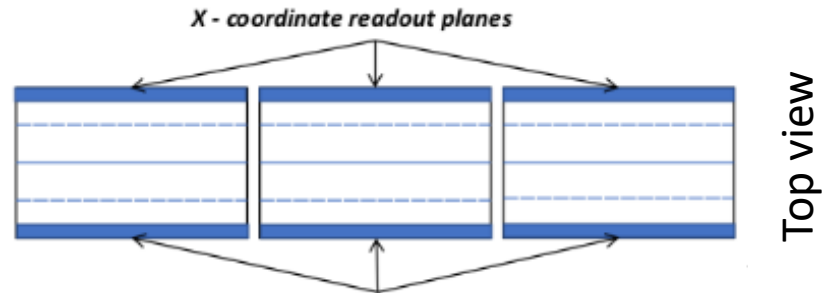
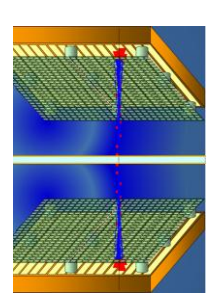


No thick frame allowed in the acceptance?

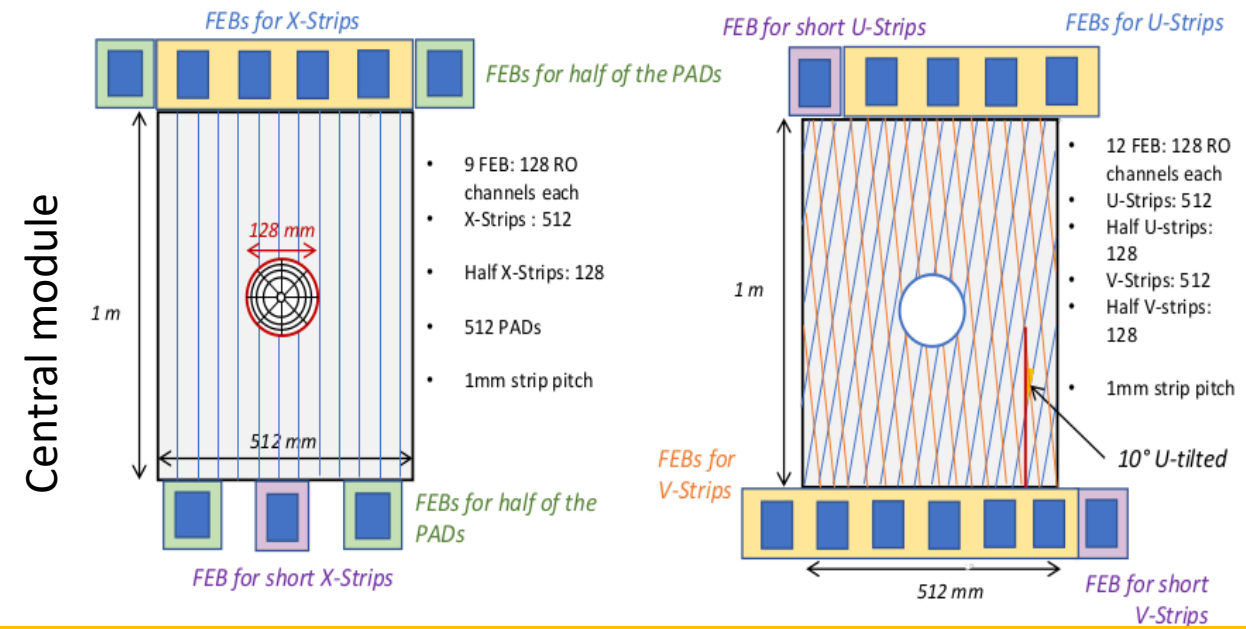
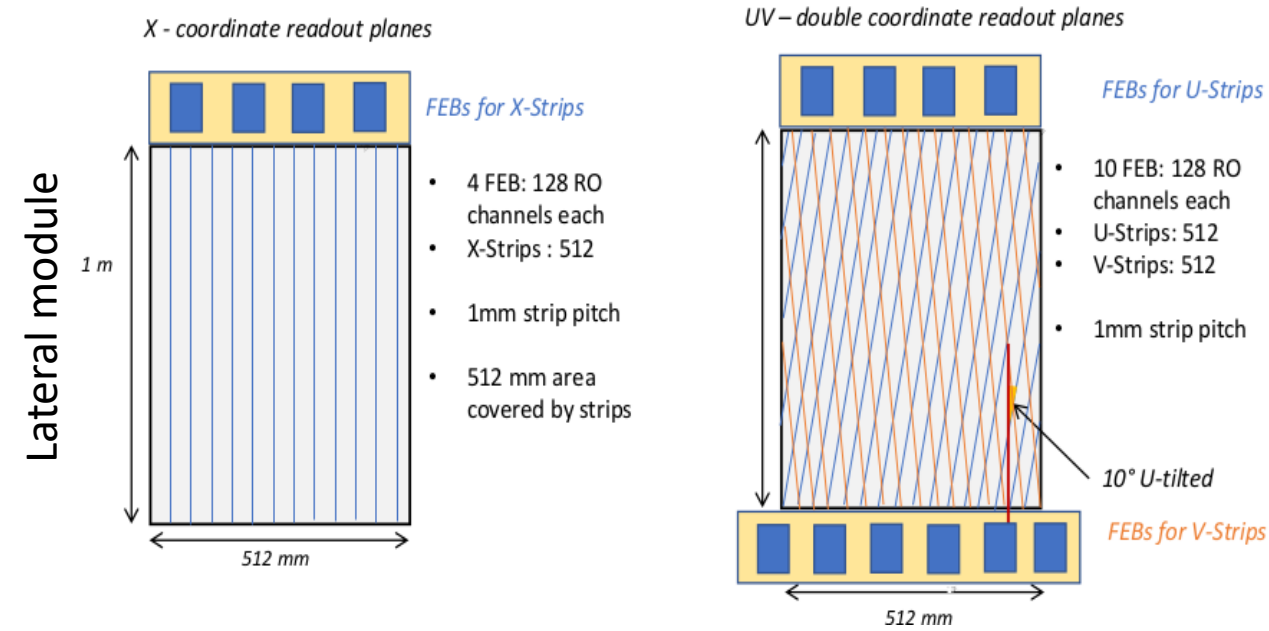


# Concept design (2)

- common cathode design
- 2 types of modules with different anodes

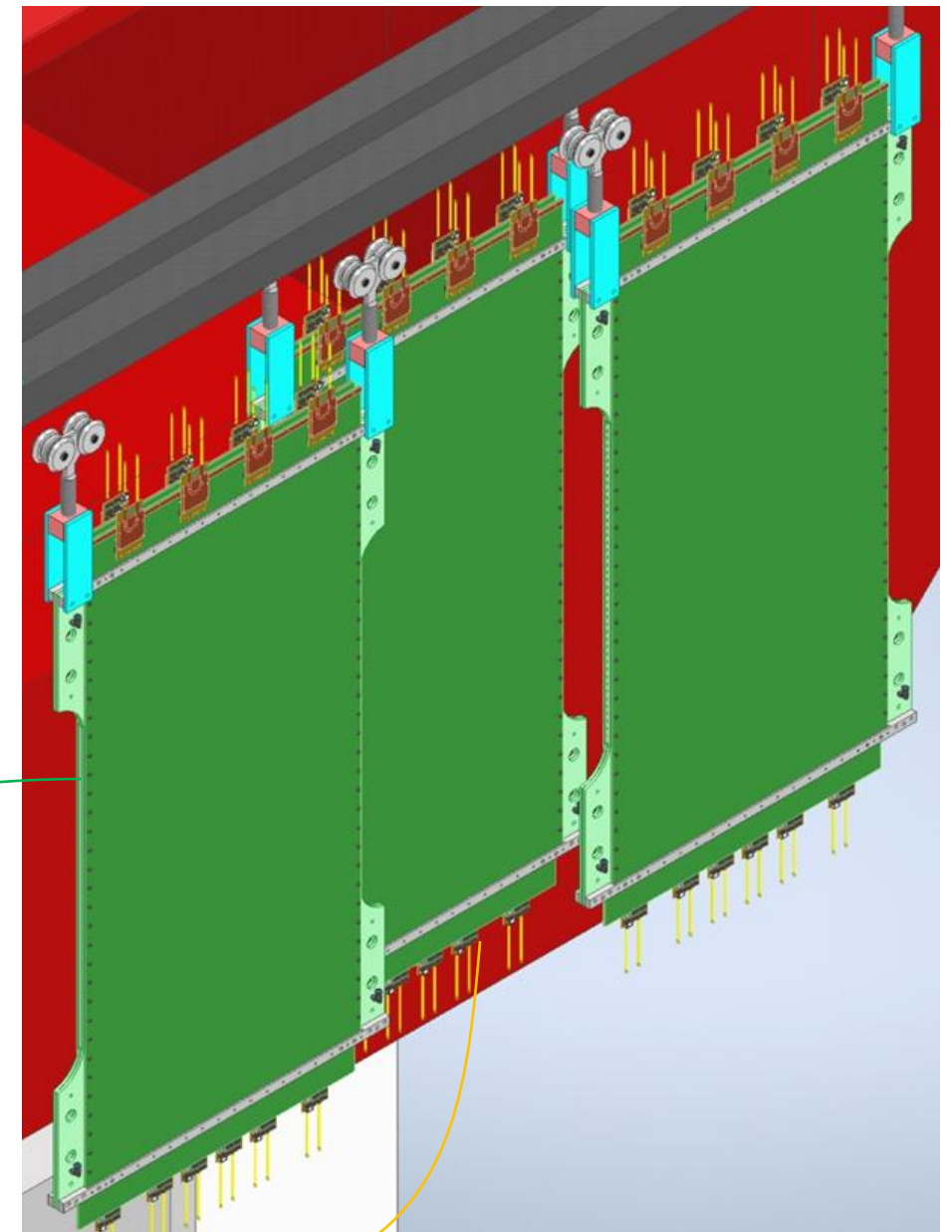
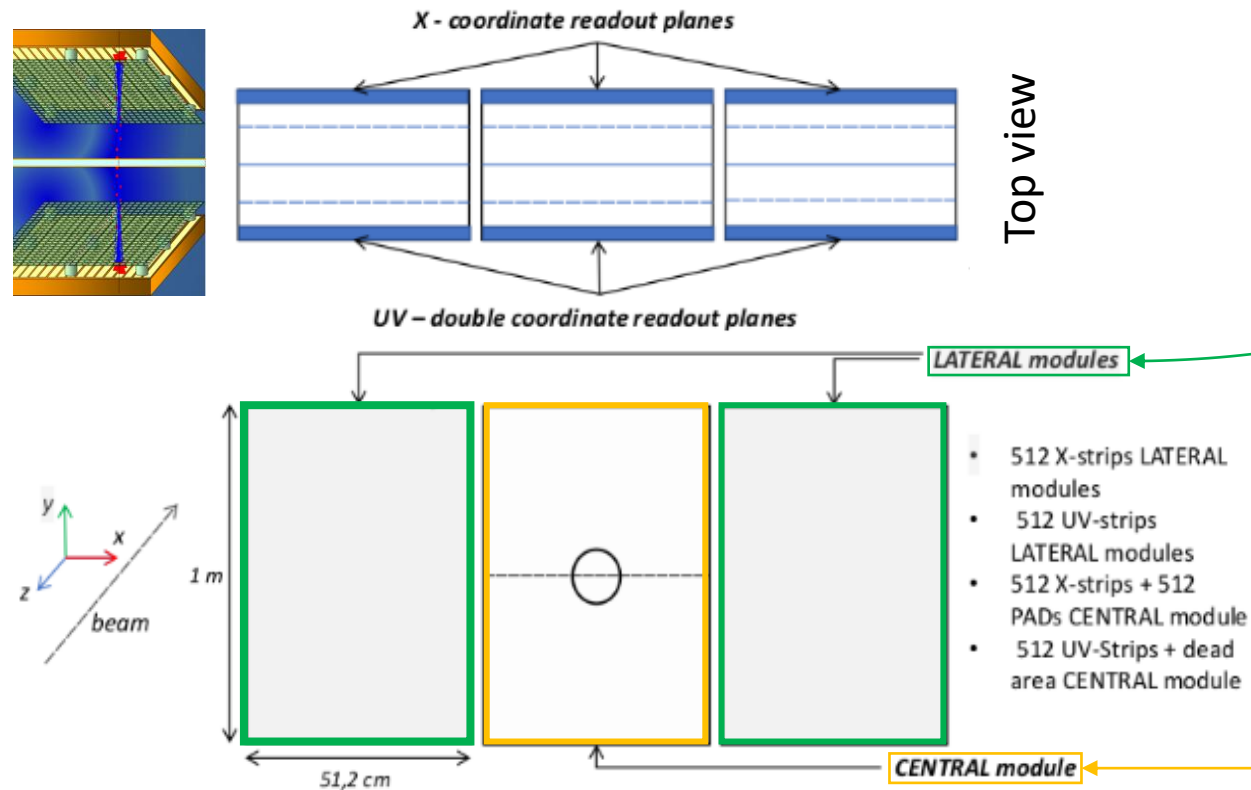


22/09/2025



# Concept design (2)

- common cathode design
- 2 types of modules with different anodes



# Concept design (3)

X shielding and connector layer : 35um copper

-3.2mm Glass epoxy

X strip layer : 35um Copper

-50um Prepreg

-50um Kapton

X DLC layer

-pillars 150um

X mesh: 45/18

Drift gap : 5mm

Drift mesh : 45/18

Drift gap: 5mm

U.V mesh: 45/18

-pillars 150um

U.V DLC layer

-50um Kapton

-50um Prepreg

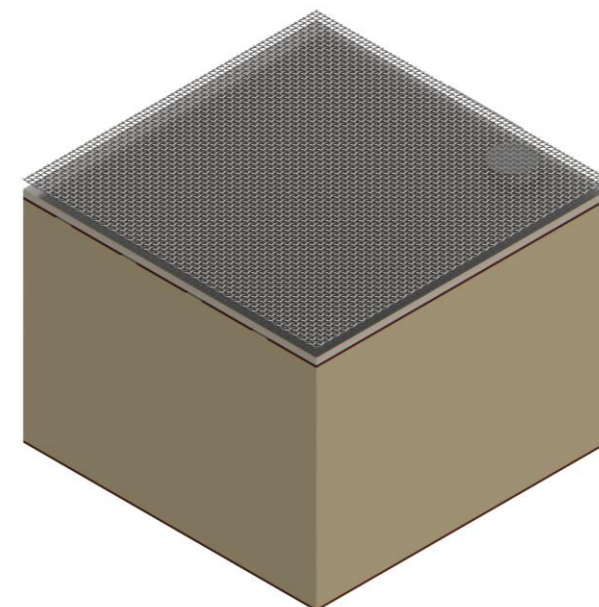
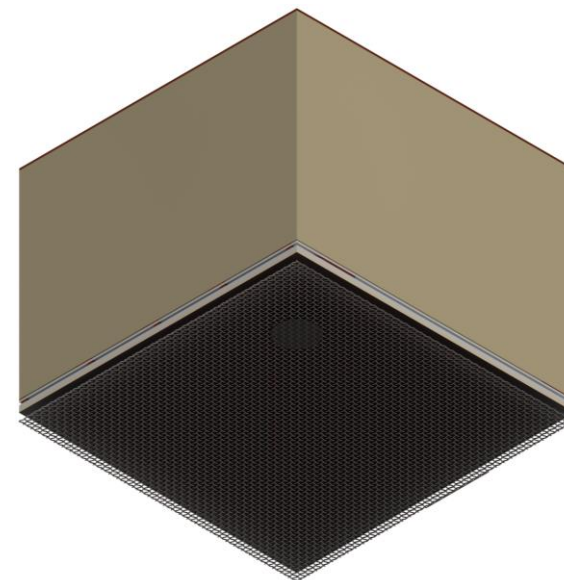
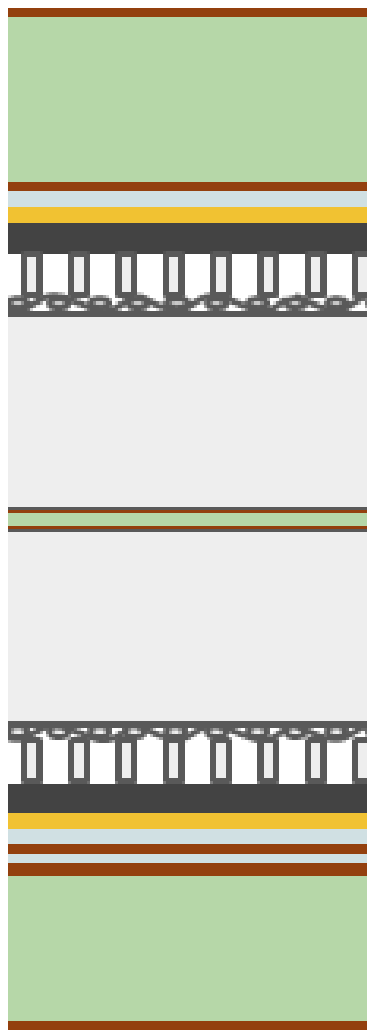
U layer: 35um Copper

-28um Prepreg

V Layer: 17um copper

-3.2mm glass epoxy

U.V bottom shielding and connector layer: 35um copper





# Concept design (3)

X shielding and connector layer : 35um copper

-3.2mm Glass epoxy

X strip layer : 35um Copper

-50um Prepreg

-50um Kapton

X DLC layer

-pillars 150um

X mesh: 45/18

Drift gap : 5mm

Drift mesh : 45/18

Drift gap: 5mm

U.V mesh: 45/18

-pillars 150um

U.V DLC layer

-50um Kapton

-50um Prepreg

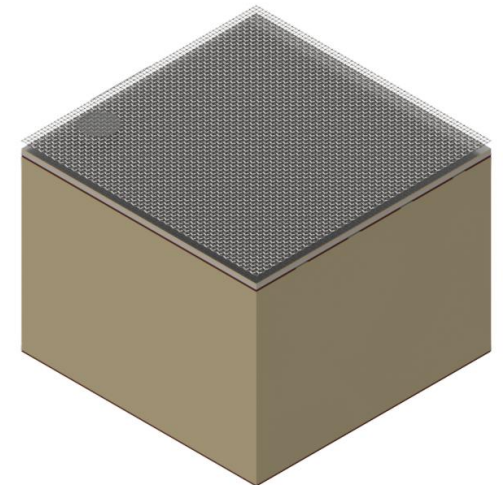
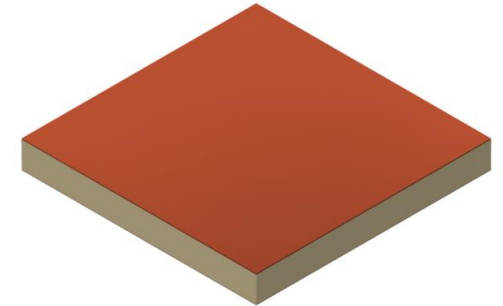
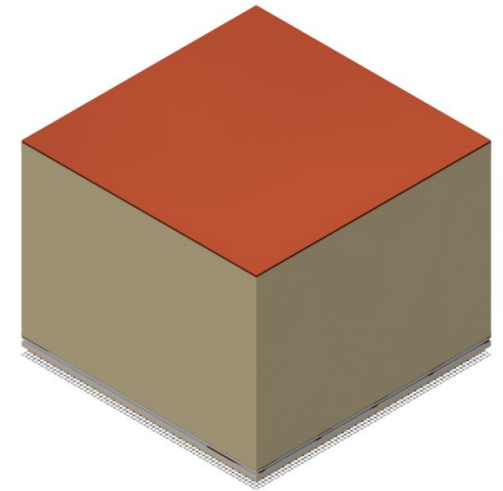
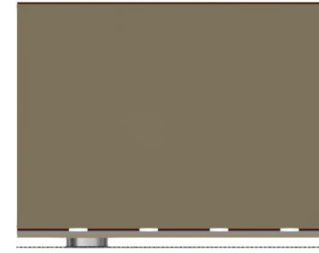
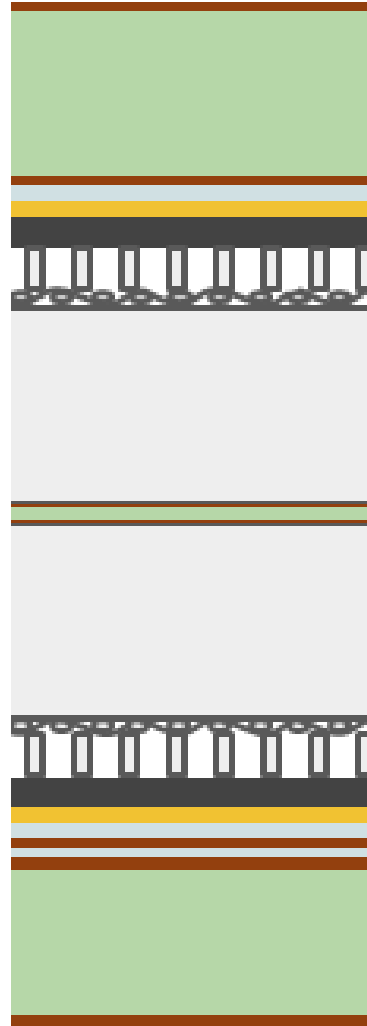
U layer: 35um Copper

-28um Prepreg

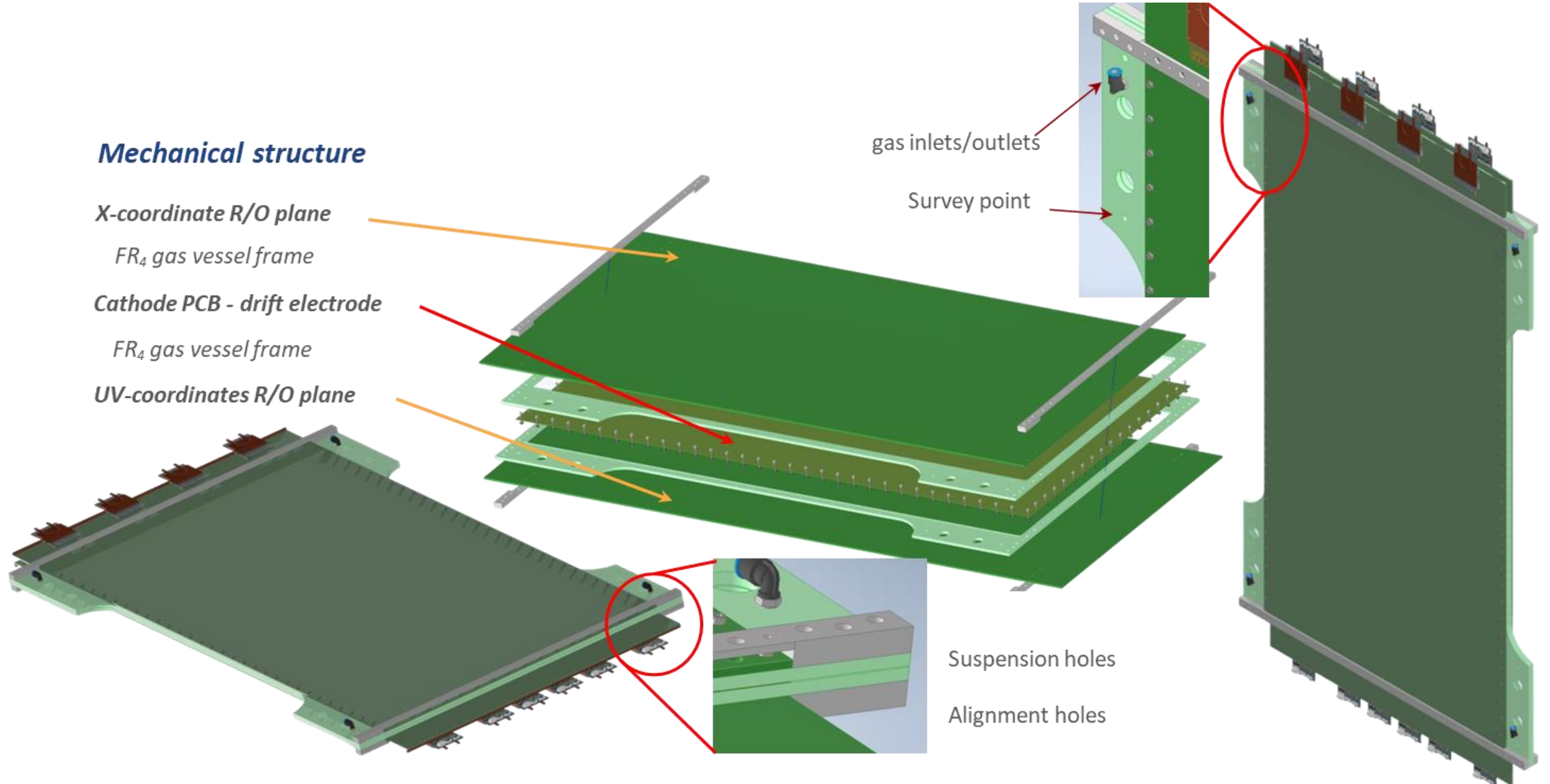
V Layer: 17um copper

-3.2mm glass epoxy

U.V bottom shielding and connector layer: 35um copper

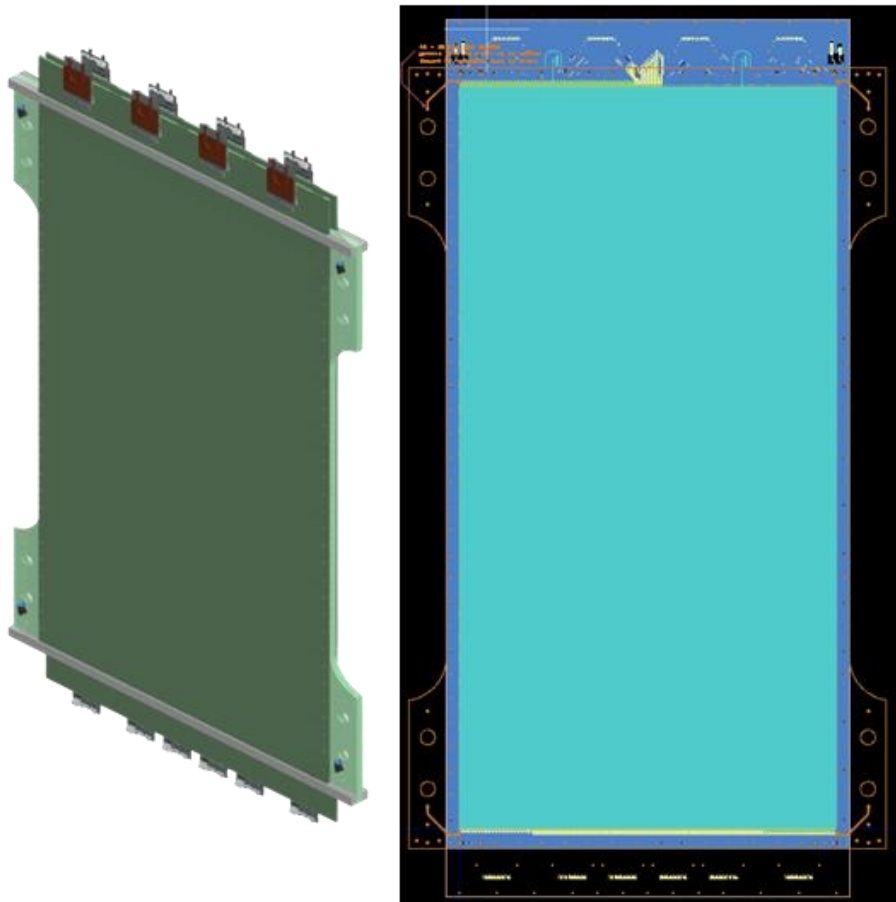


# Lateral module prototype design

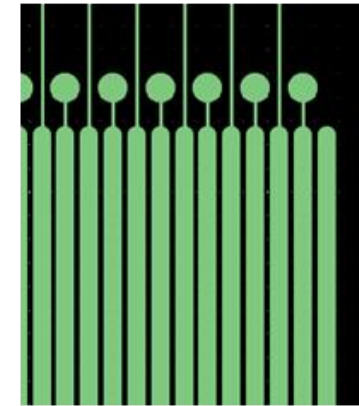
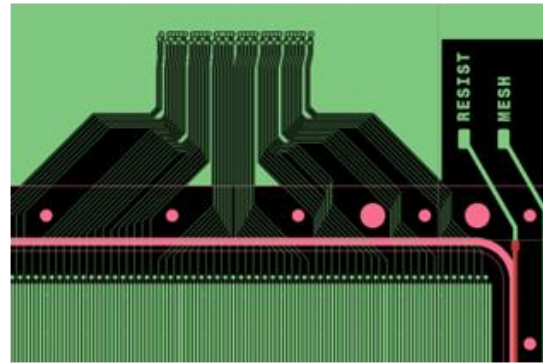


# Lateral module prototype production

## Readout PCB design and production

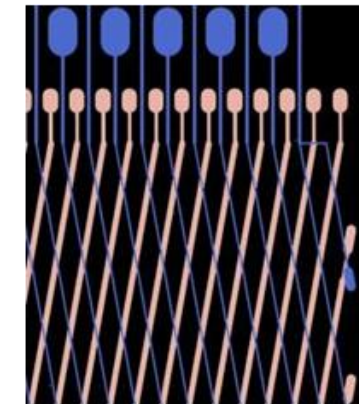
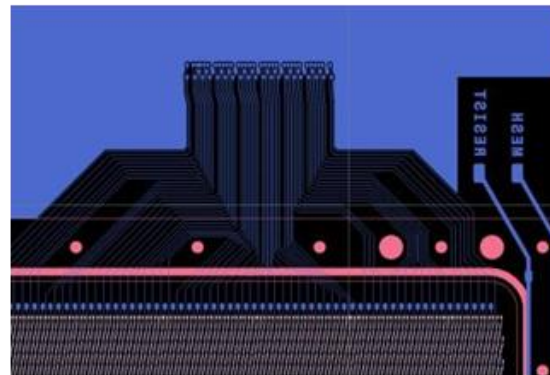


*X-coordinate R/O plane*



- 512 strips
- 1mm pitch
- 750  $\mu\text{m}$  width
- 4 FEBs: 512 fe channels

*UV-coordinate R/O plane*



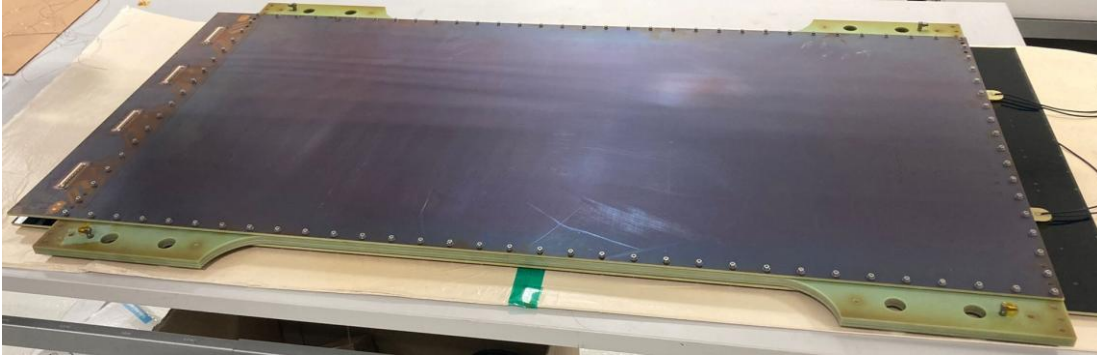
- 1280 strips
- 1mm pitch
- 250  $\mu\text{m}$  U strips width
- 150  $\mu\text{m}$  V strips width
- 10 FEBs: 1280 fe channels



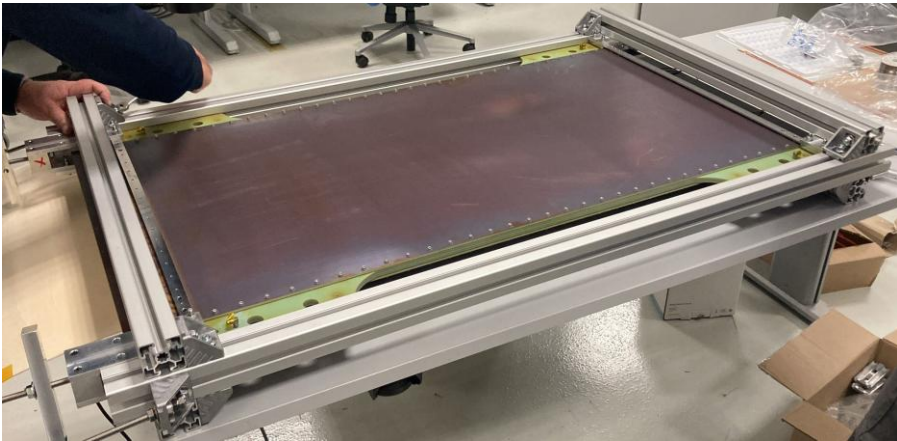


# Lateral module prototype testing

Delivered on 11.10.24



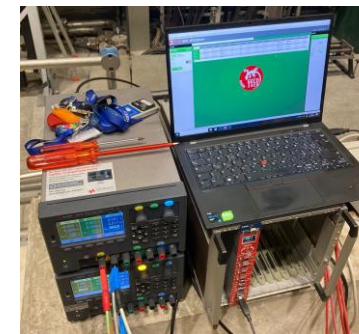
Mechanics for transport and suspension mounted  
11.10.24



Transported and installed in the AMBER experiment  
12.10.24



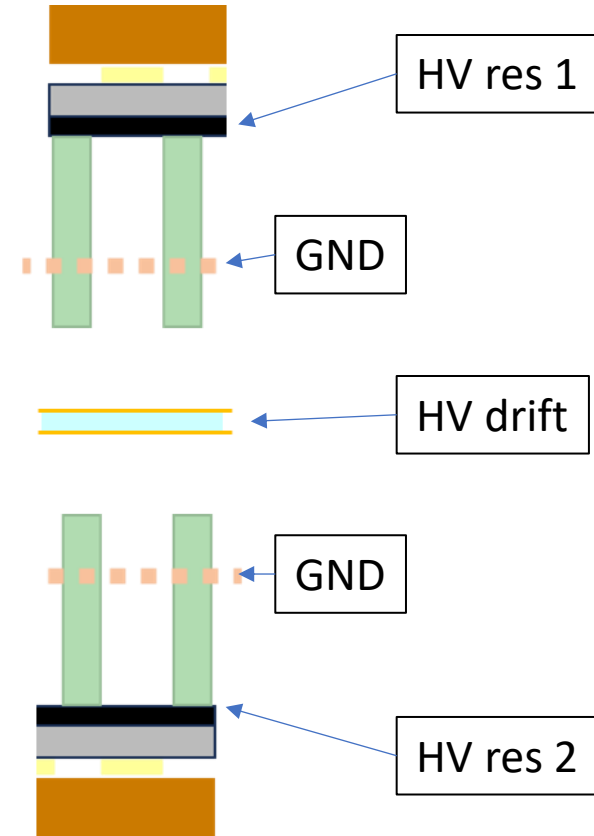
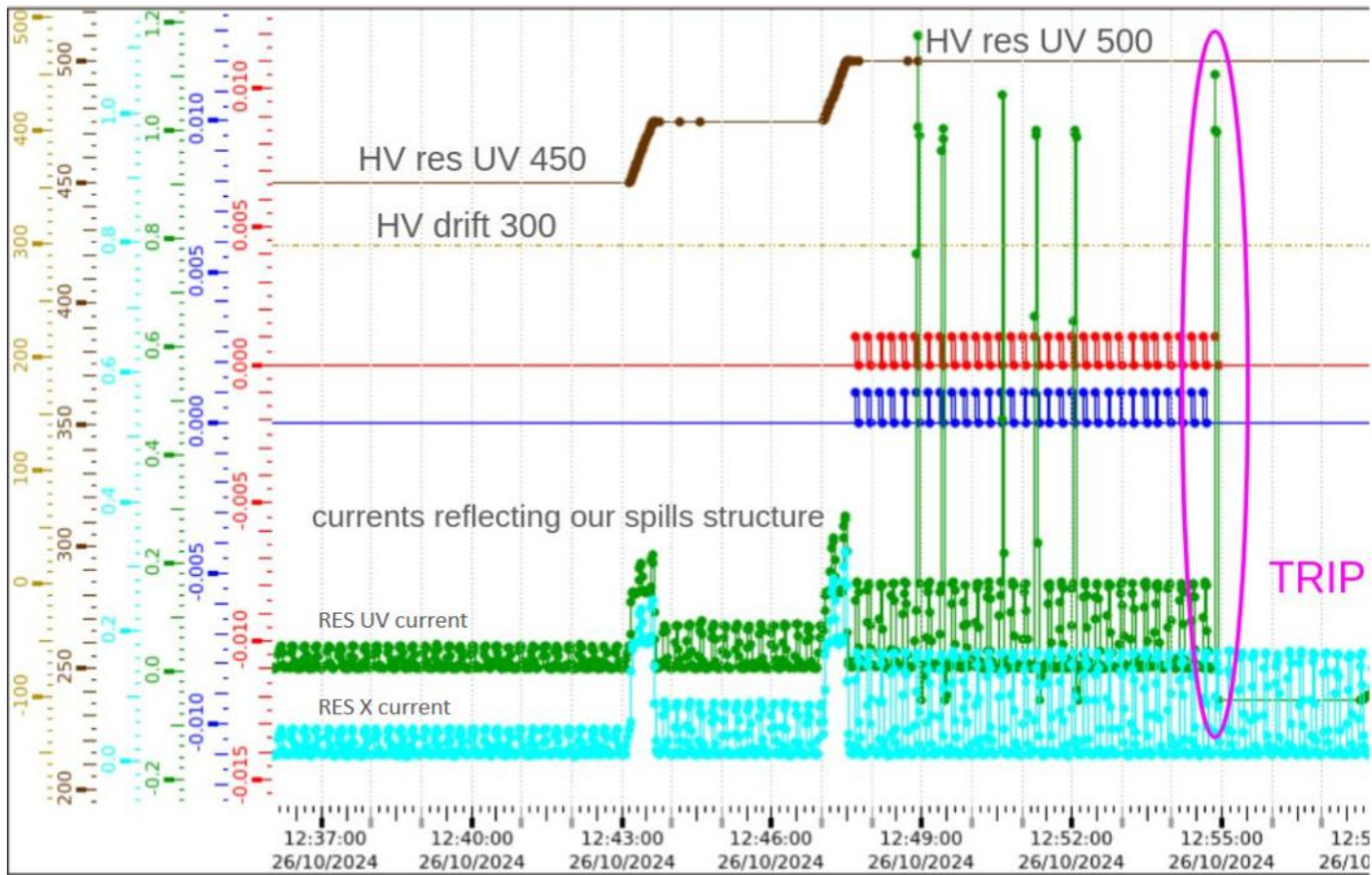
HV stability verified by MPT workshop experts  
17.10.24



450V resistive layers  
325V cathodes planes  
resistive UV  $\sim 5\text{nA}$   
resistive X  $\sim 7\text{nA}$   
drift UV  $\sim 1,5\text{nA}$   
drift X  $\sim 3\text{nA}$

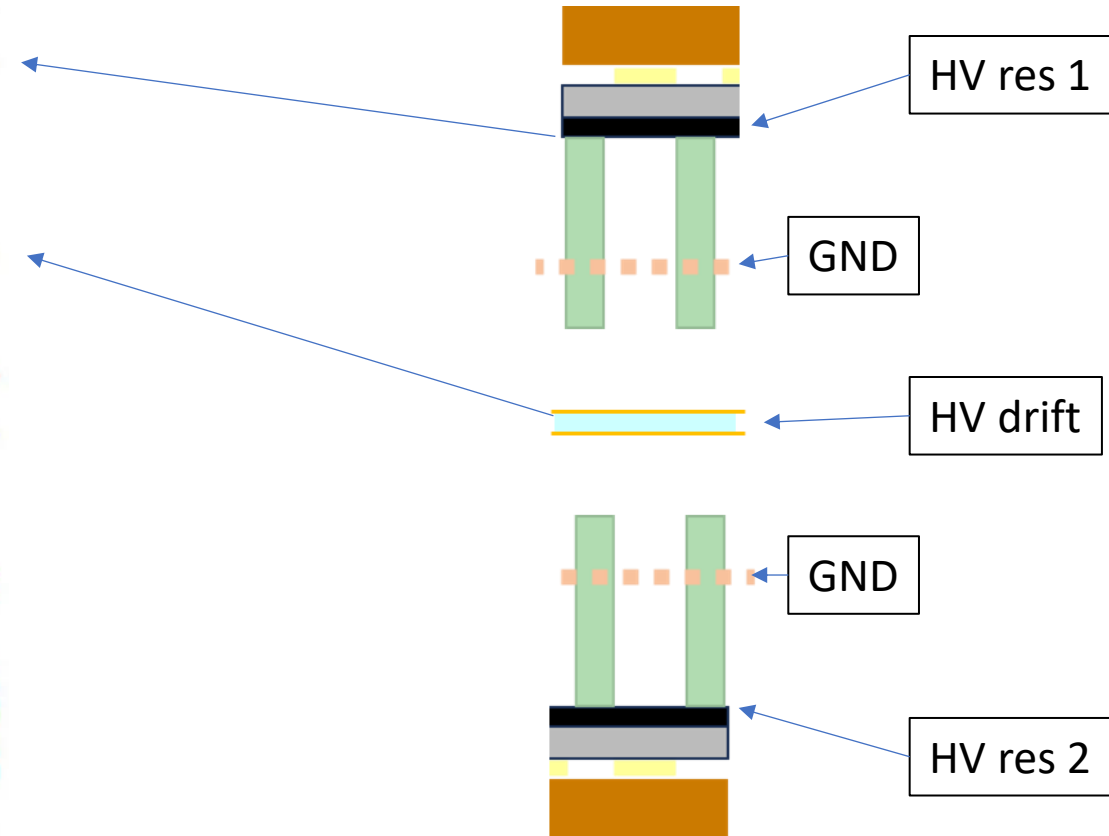
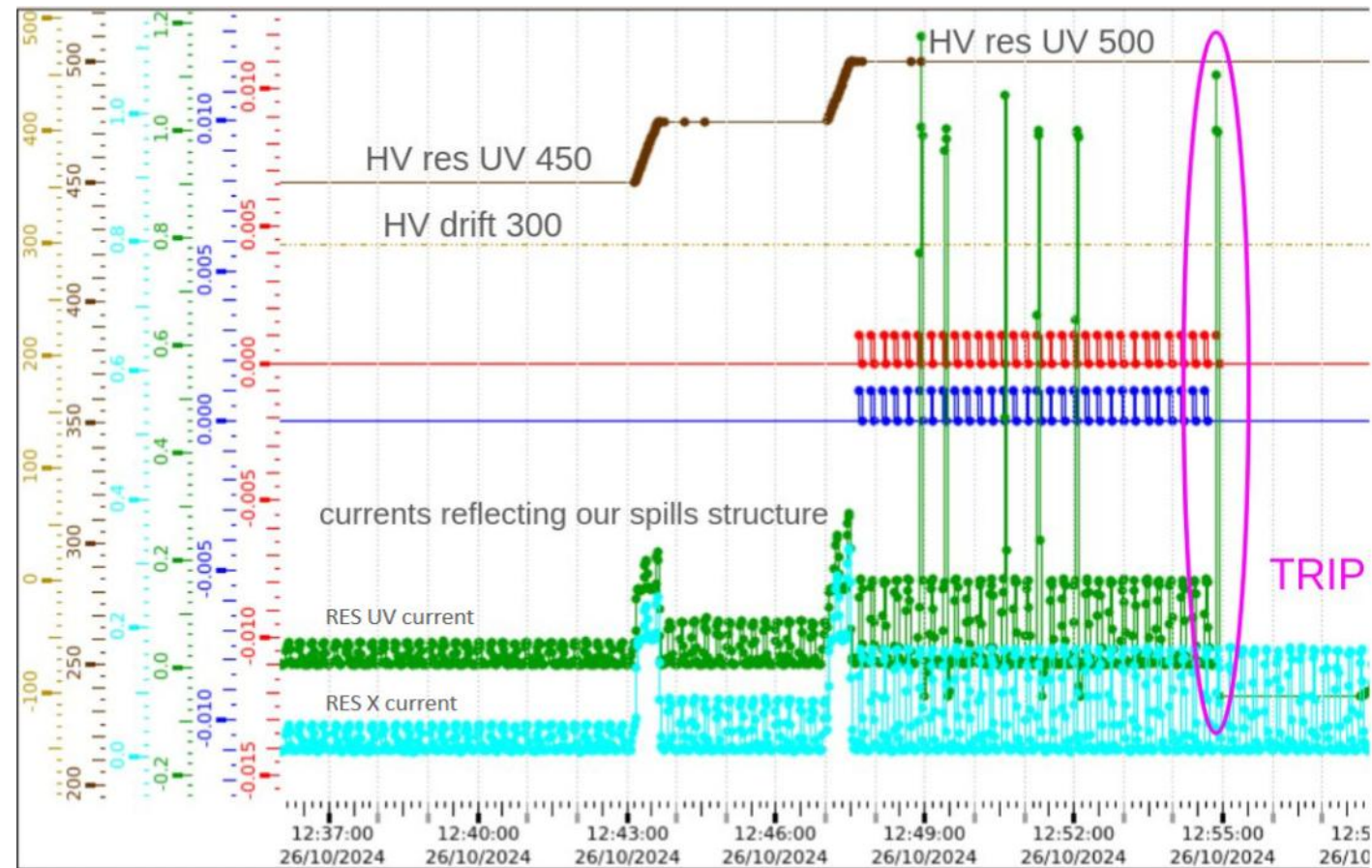
***We express our gratitude to MPT and GDD labs colleagues and all the community that supports us in the task***

# Glimpse of the first operation 1



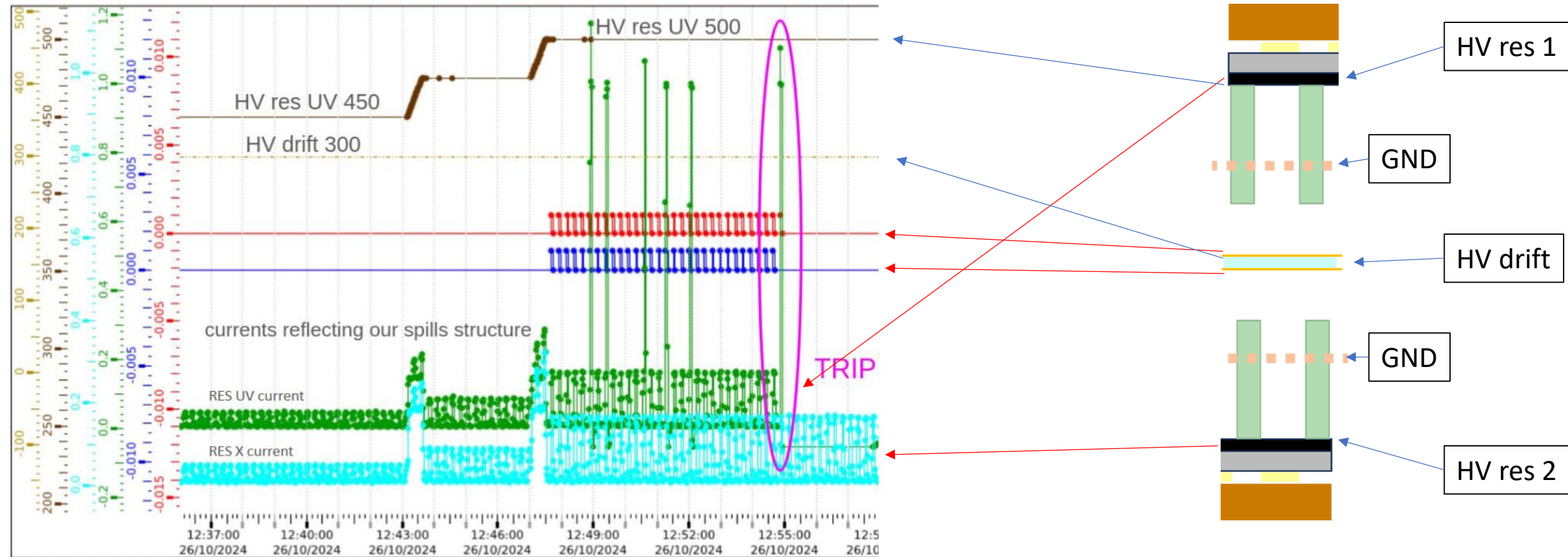
Some trips were observed only in the initial operation period

# Glimpse of the first operation 1





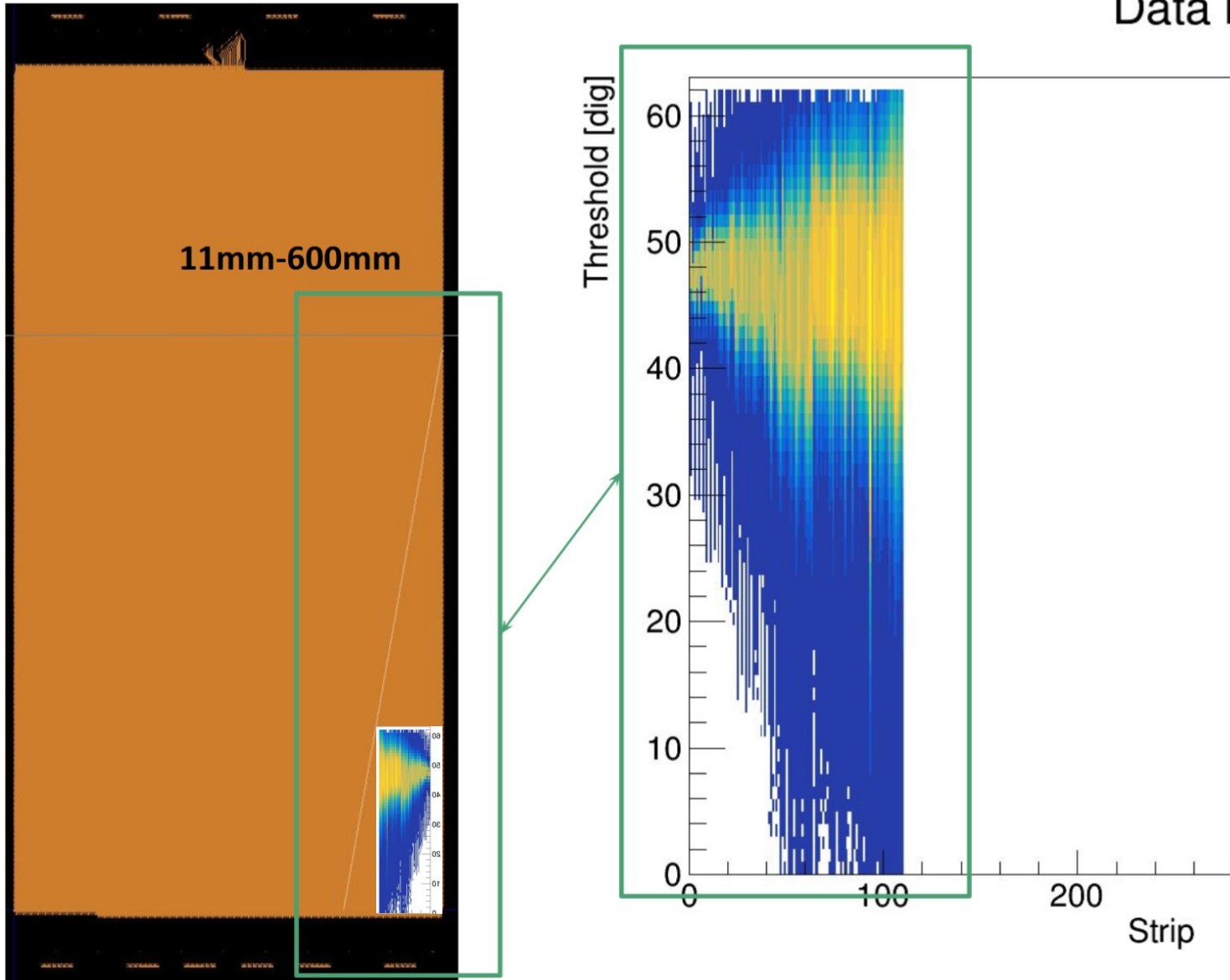
# Glimpse of the first operation 1



Gas gain was observed as expected

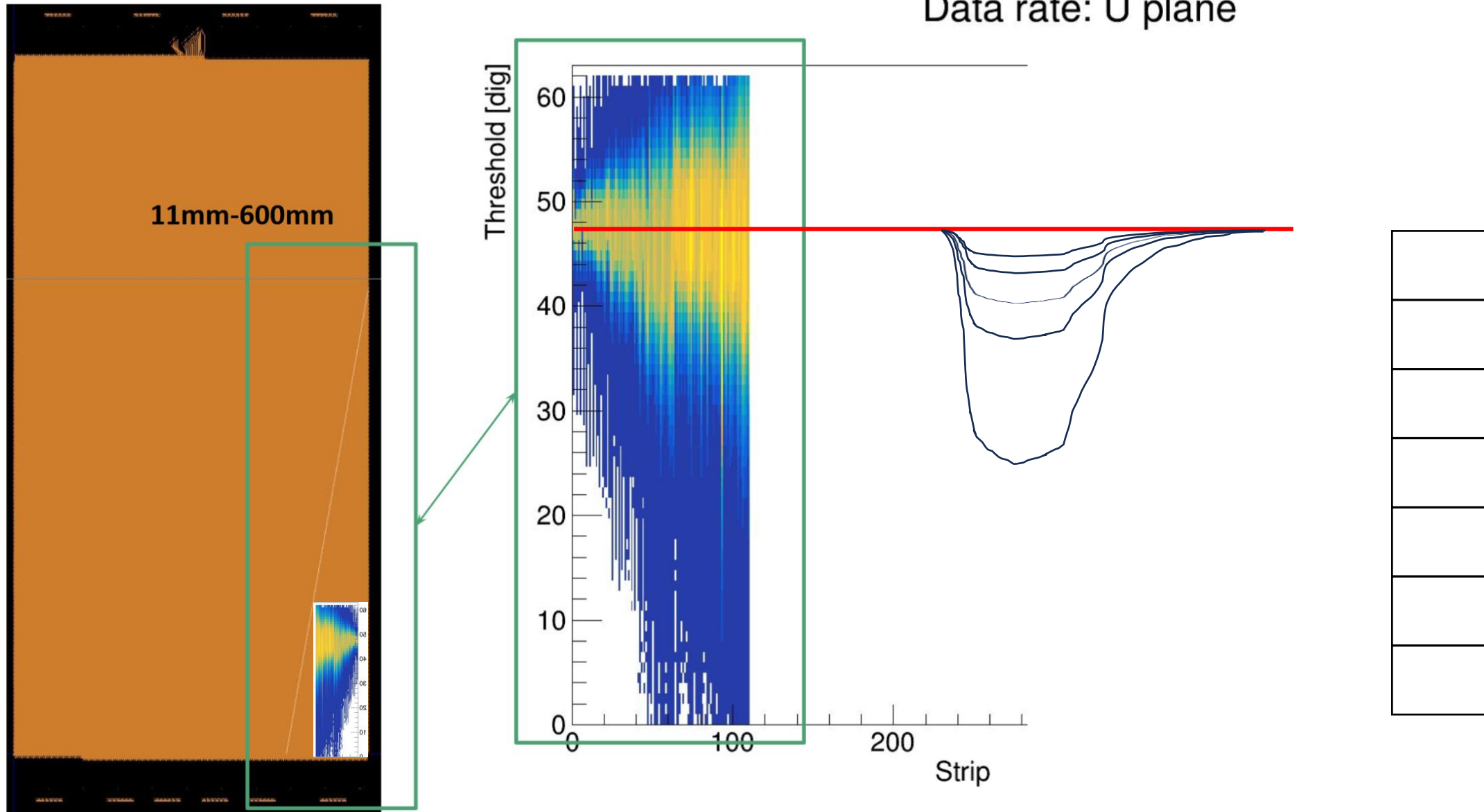
# Glimpse of the first operation 2

Data rate: U plane



# Glimpse of the first operation 2

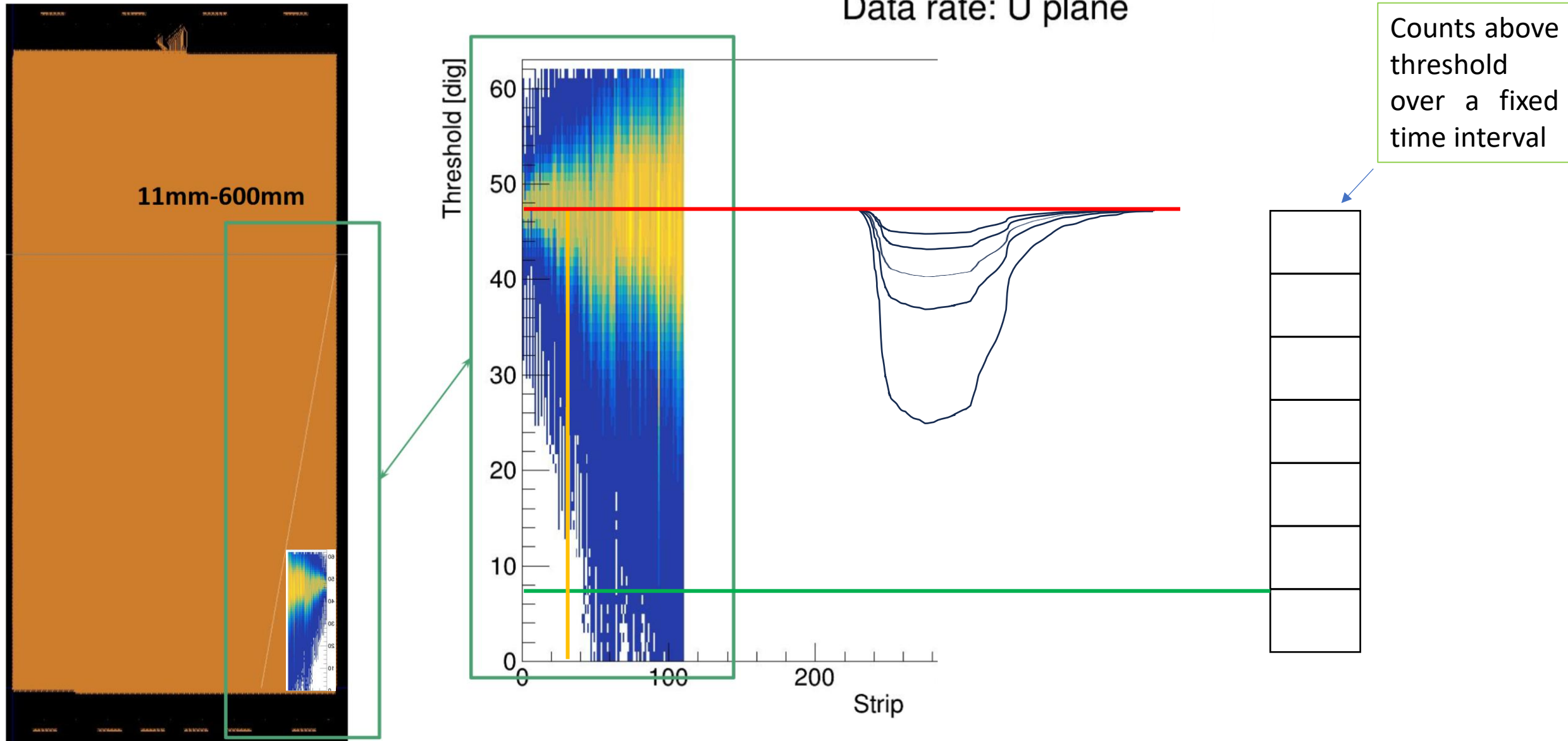
Data rate: U plane





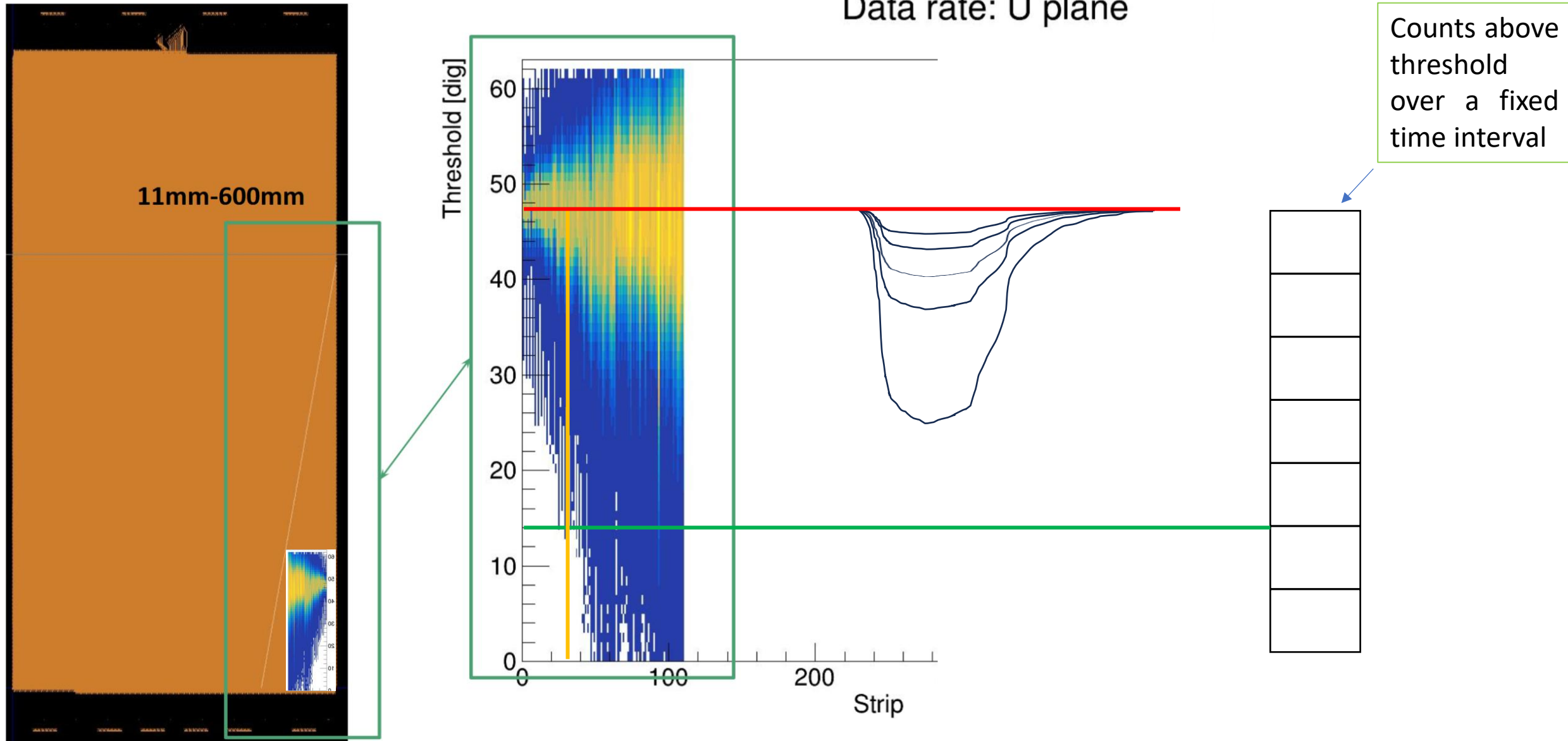
# Glimpse of the first operation 2

Data rate: U plane



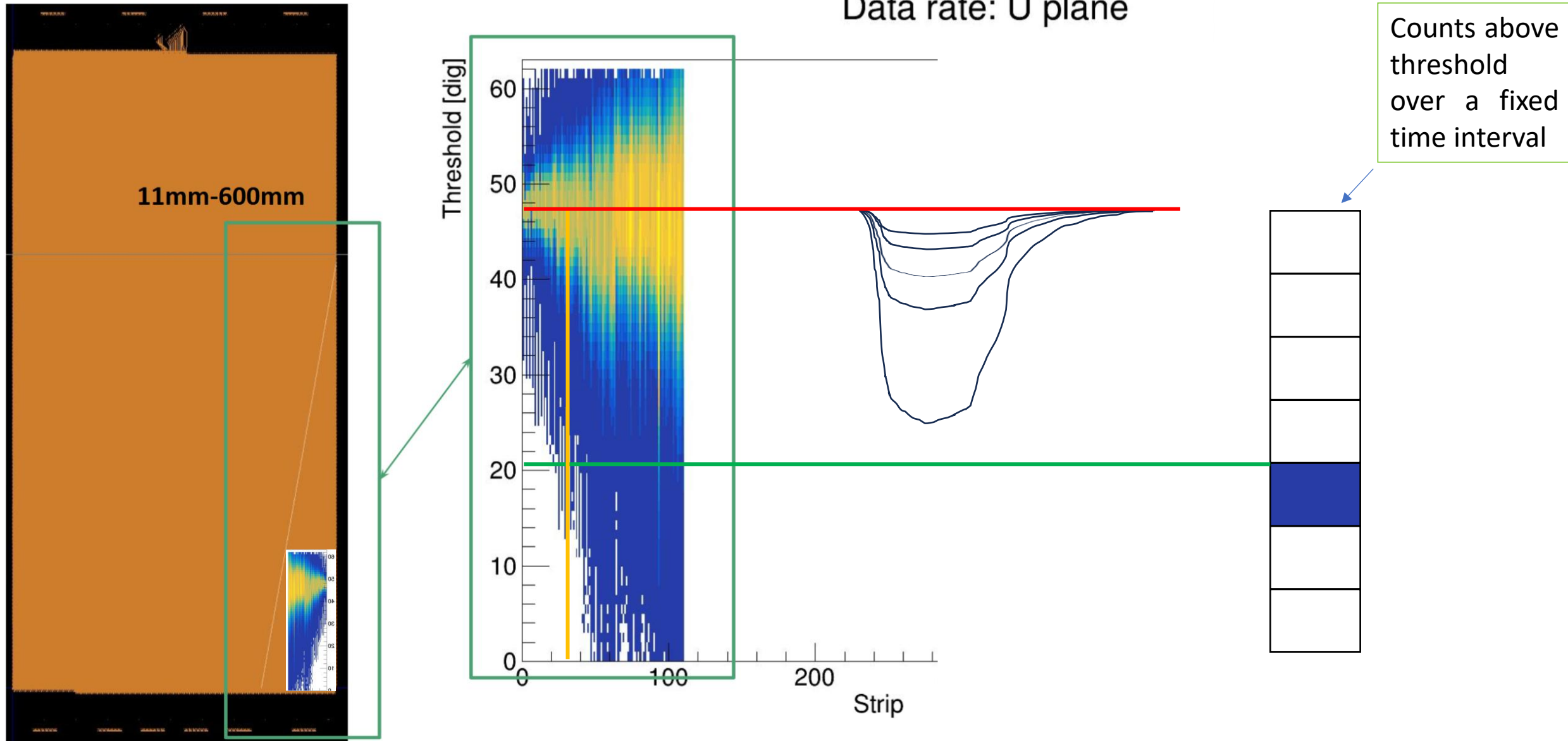
# Glimpse of the first operation 2

Data rate: U plane



# Glimpse of the first operation 2

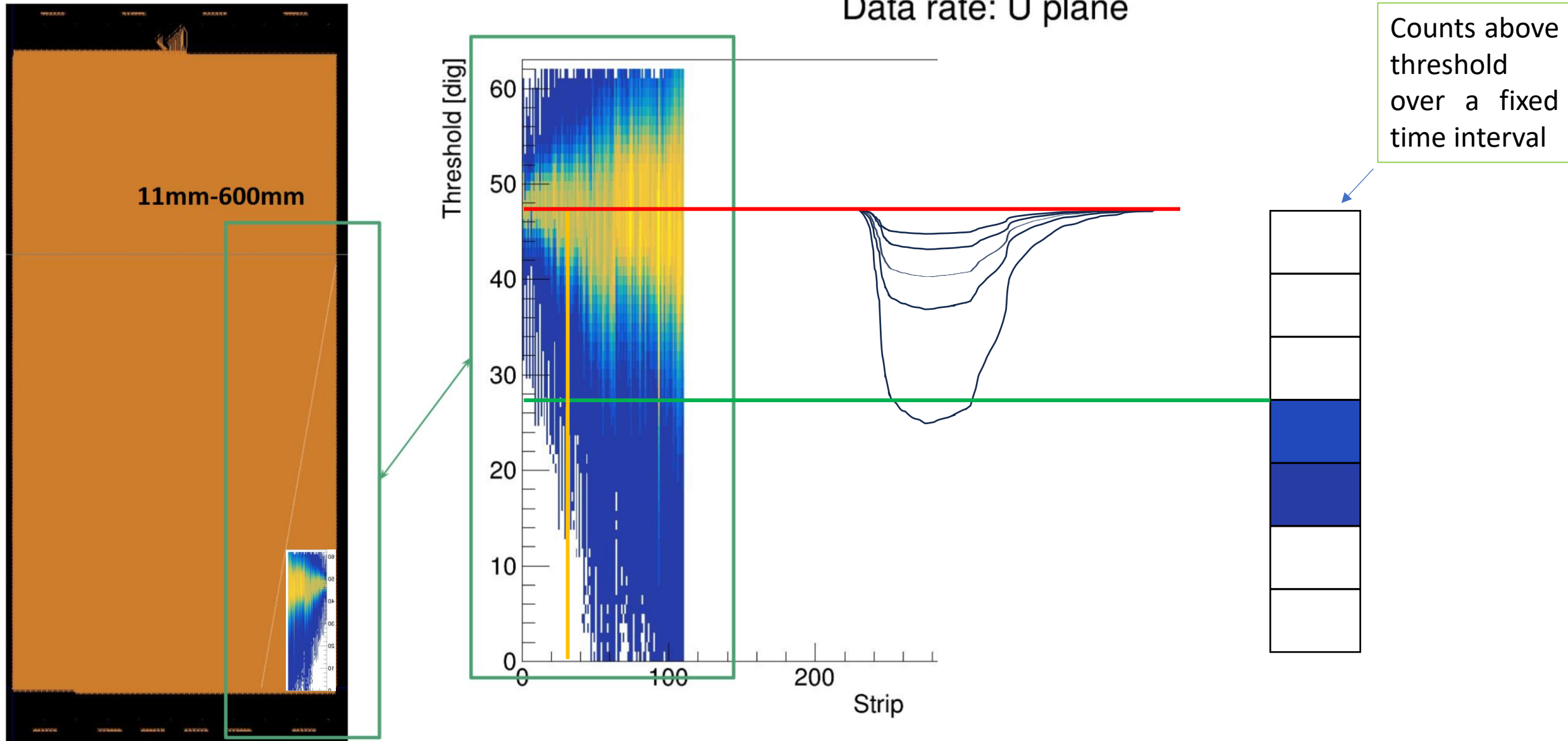
Data rate: U plane





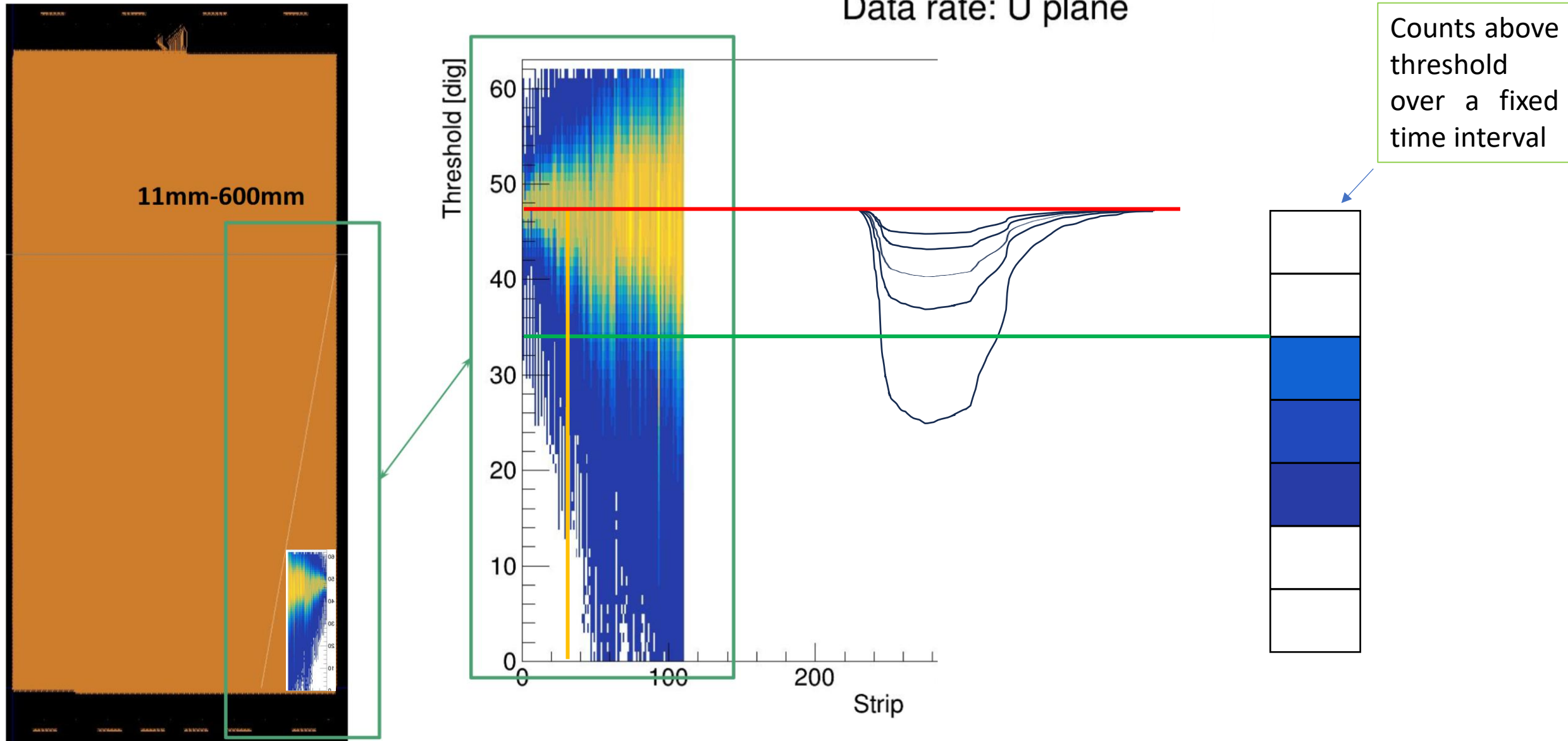
# Glimpse of the first operation 2

Data rate: U plane



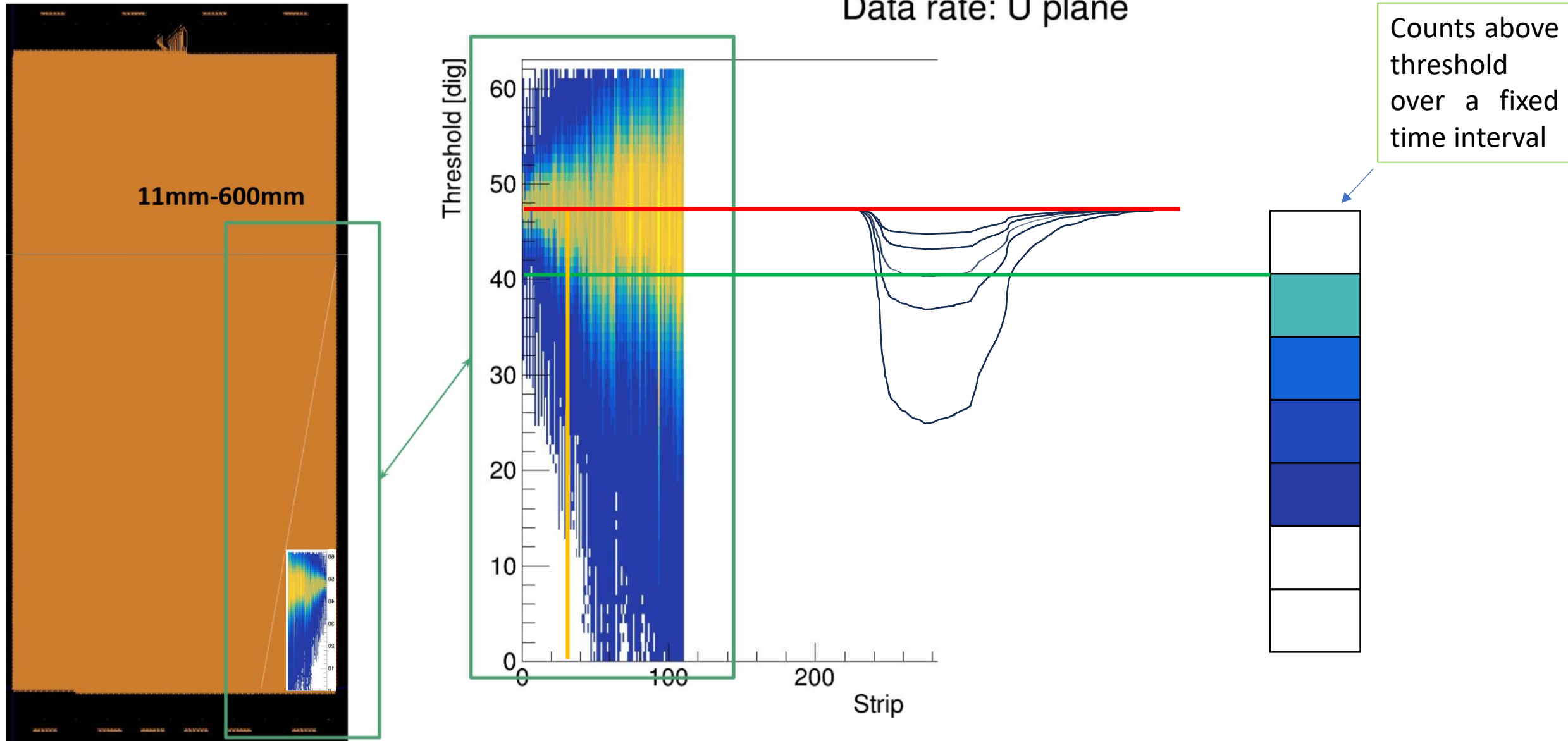
# Glimpse of the first operation 2

Data rate: U plane



# Glimpse of the first operation 2

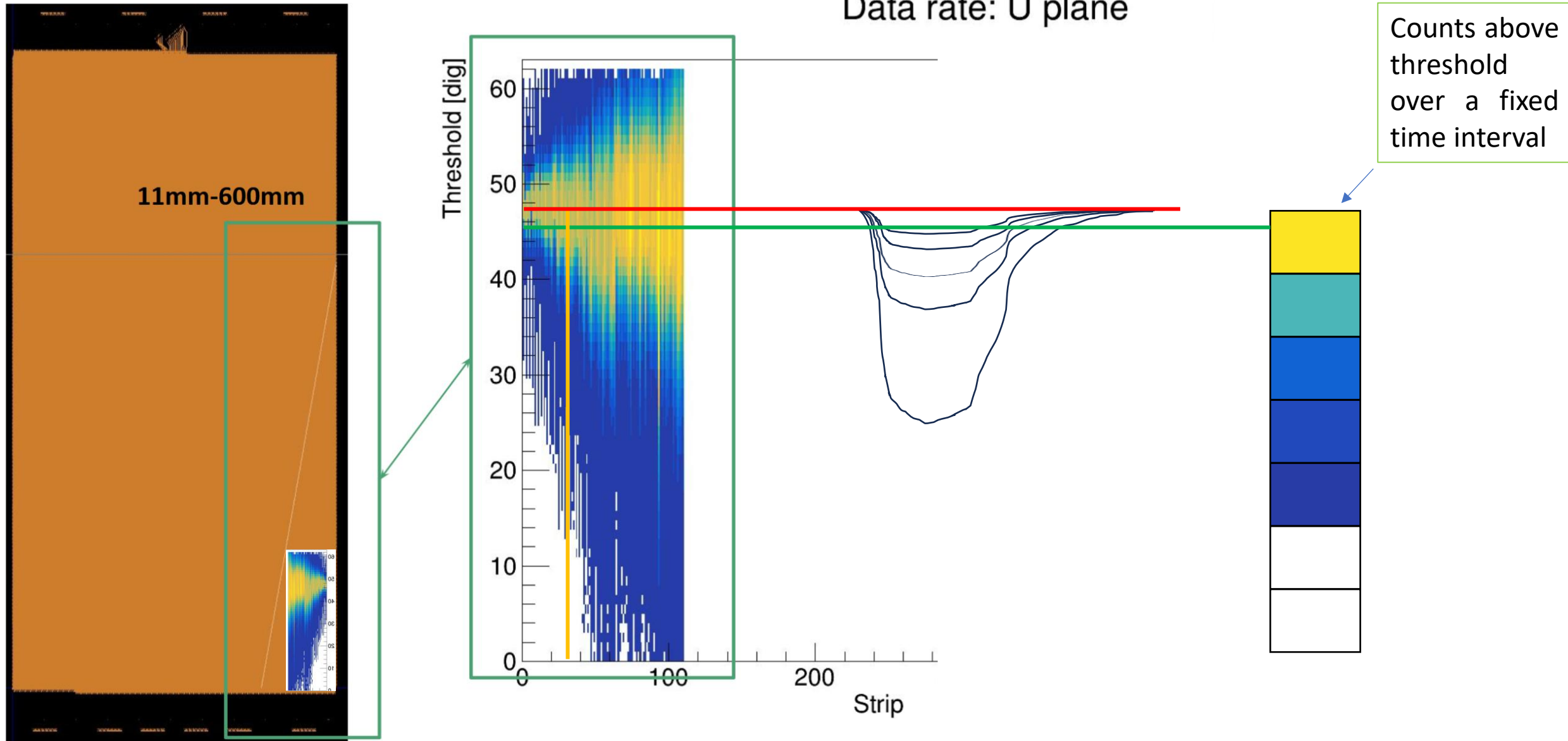
Data rate: U plane





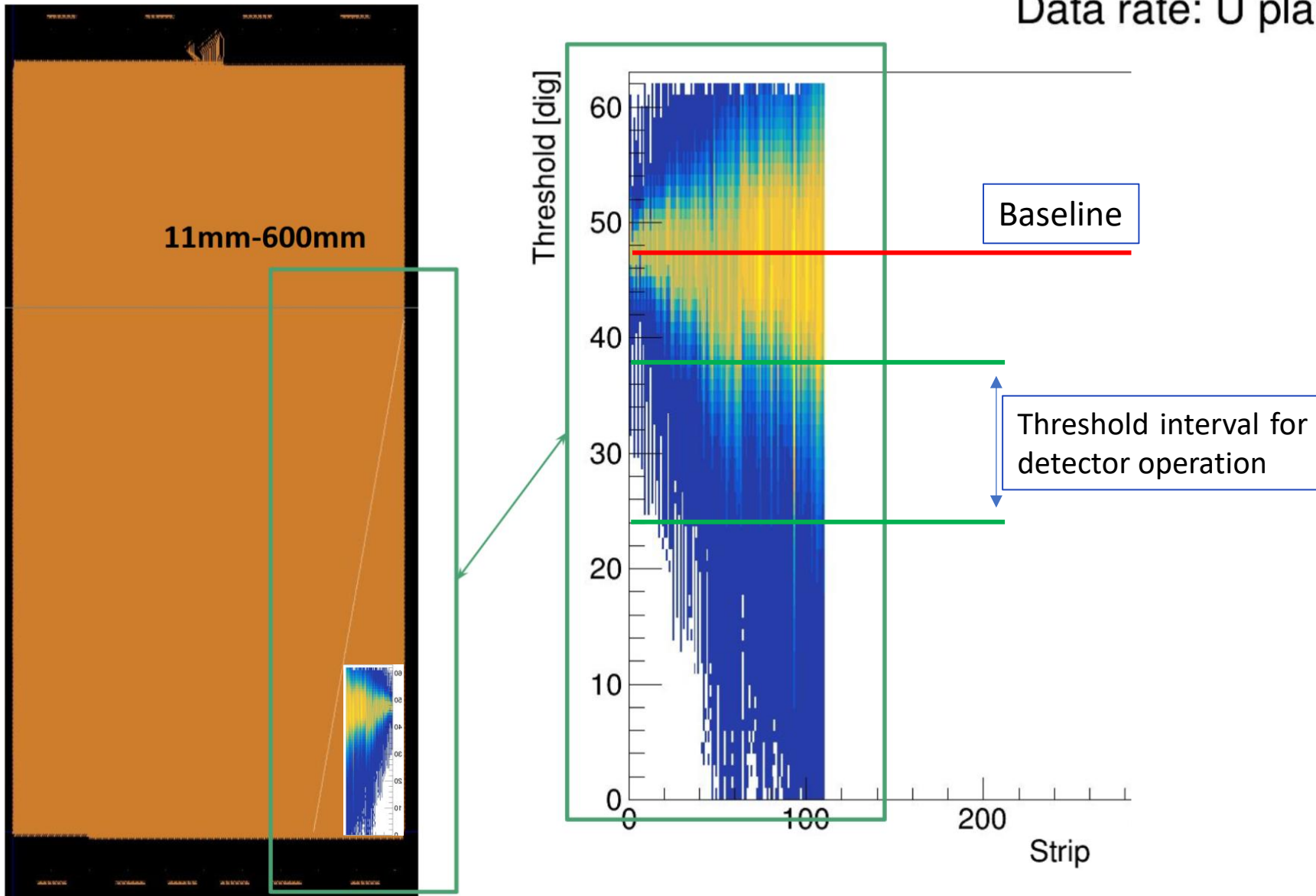
# Glimpse of the first operation 2

Data rate: U plane



# Glimpse of the first operation 3

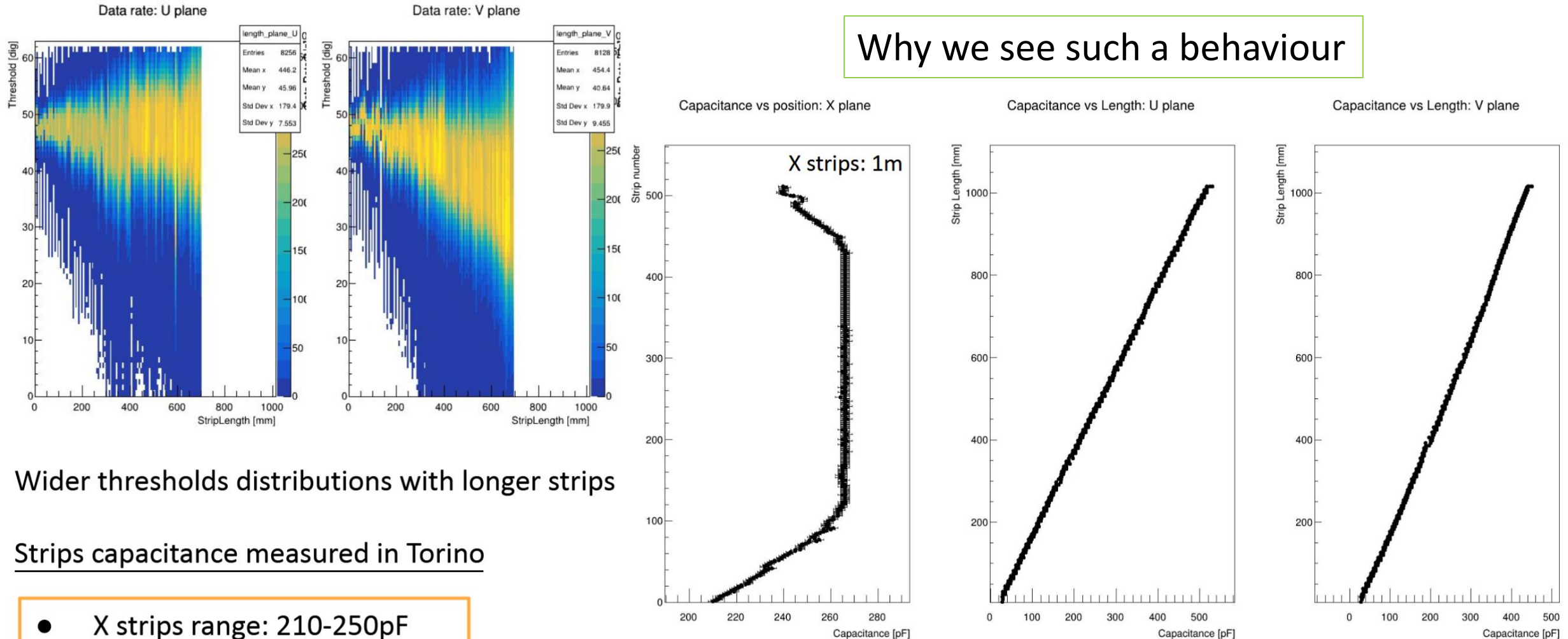
Data rate: U plane



- Data tacking only possible on the short strips
- Unexpected behaviour to be understood and corrected

# Glimpse of the first operation 4

Why we see such a behaviour



Wider thresholds distributions with longer strips

Strips capacitance measured in Torino

- X strips range: 210-250pF
- U strips range: 30-530pF
- V strips range: 28-450pF

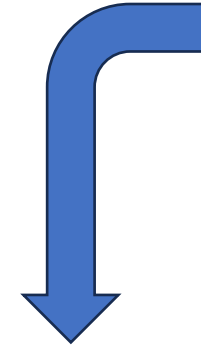
We had to update the ASIC design features



# Torino Readout for AMBER (ToRA) ASIC

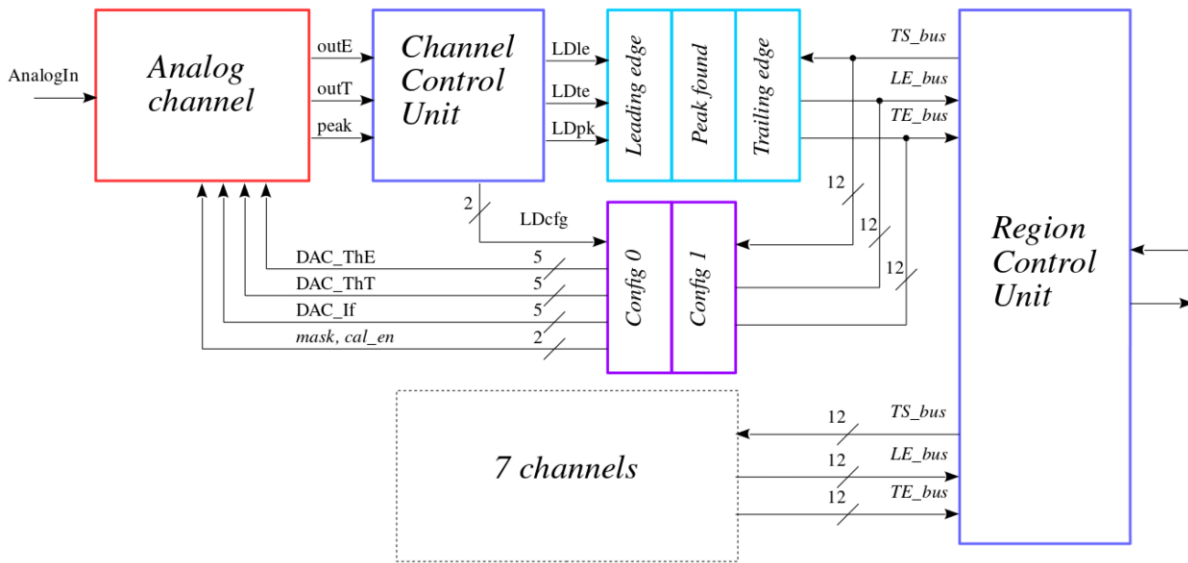
- MPGD and Wire detectors compatible
- Target specific application
- Limited complexity
- Reuse existing solutions
- 65nm
- 2 step design

Detector	MM	Straw	
Channels/ASIC	64	64	
Power/channel	$\leq 5$	$\leq 10$	mW
Input capacitance	$\leq 550$	20-100	pF
Input charge	1-100	1-1000	fC
Input impedance	$\leq 50 \Omega$	<i>tbd</i>	$\Omega$
Max rate	$\leq 2$	$\leq 0.18$	MHz
Peaking time	150	75-150	ns
Time resolution	1-2	$\leq 1$	ns
Charge resolution	8	10	bits
Gain	12	2	mV/fC
ENC @10 pF	500-1000		$e^-$
ENC @150 pF	1000-2000		$e^-$
ENC @60 pF		3000	$e^-$
Threshold range	<i>tbd</i>	0-15	fC
Clock frequency	200	200	MHz

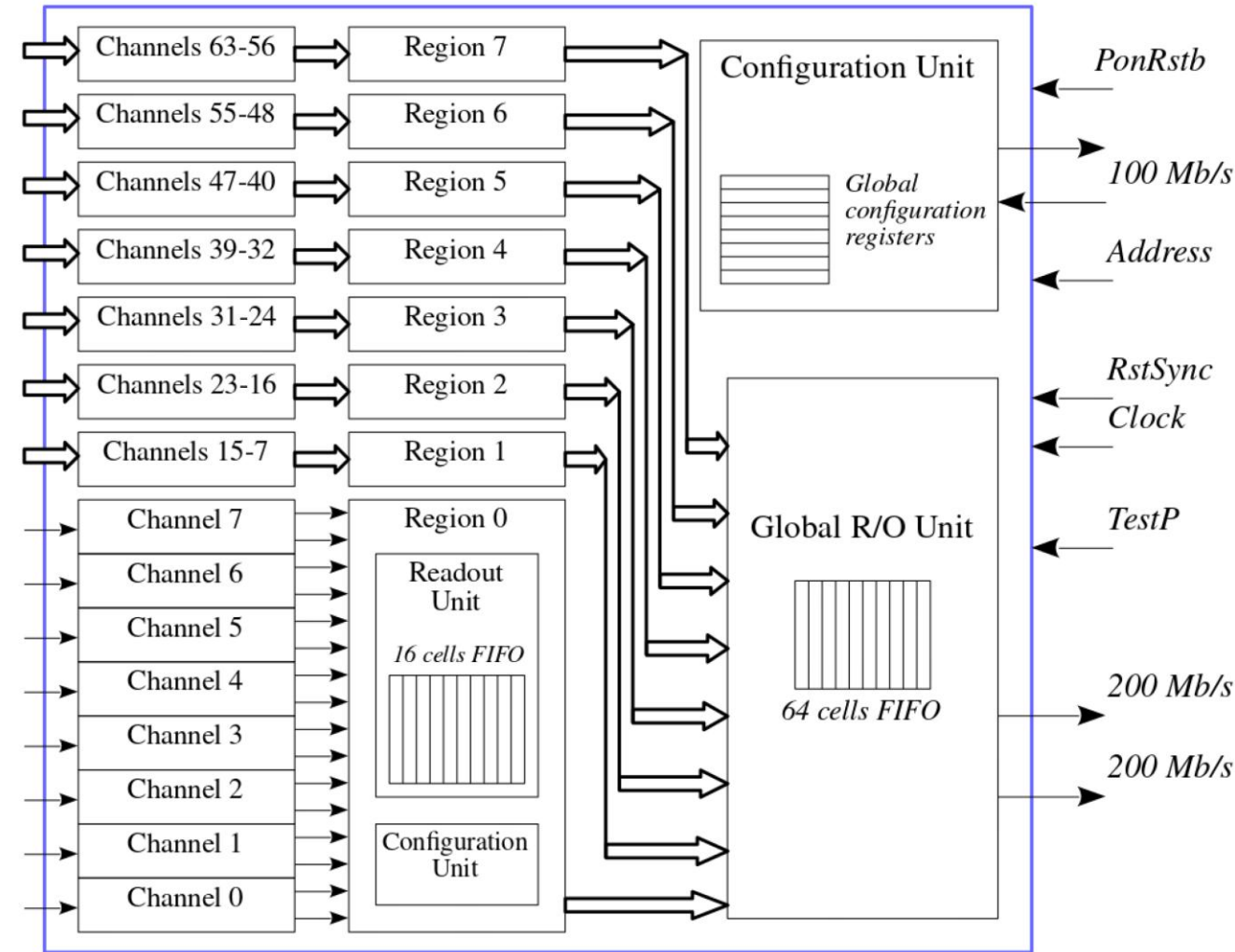


Channels	64		
Size	$4.3 \times 2.6$	$\text{mm}^2$	
Power	640	mW	
Supply voltage	1.2	V	
Gain	2,6,9,12	mV/fC	
Peaking time	25,50,150,250	ns	
Main clock	200	MHz	
Time resolution	1.44	ns	r.m.s.
Input polarity	both		

# ASIC structure



- Common time stamp distributed to all channels
- 3 data registers for time acquisition
- 2 configuration registers
- Threshold and discharge current fine tuning



# Analog part (single channel)

## ➤ Charge Sensitive Amplifier

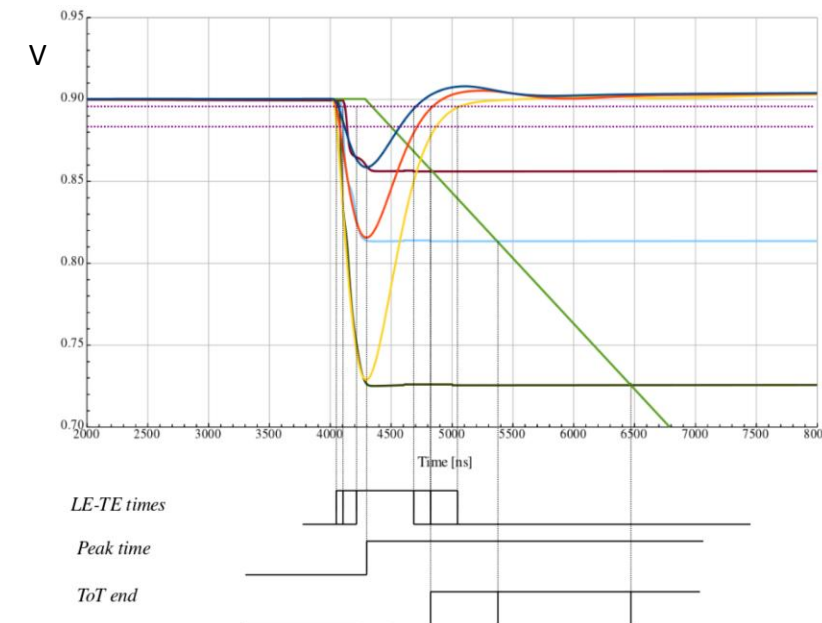
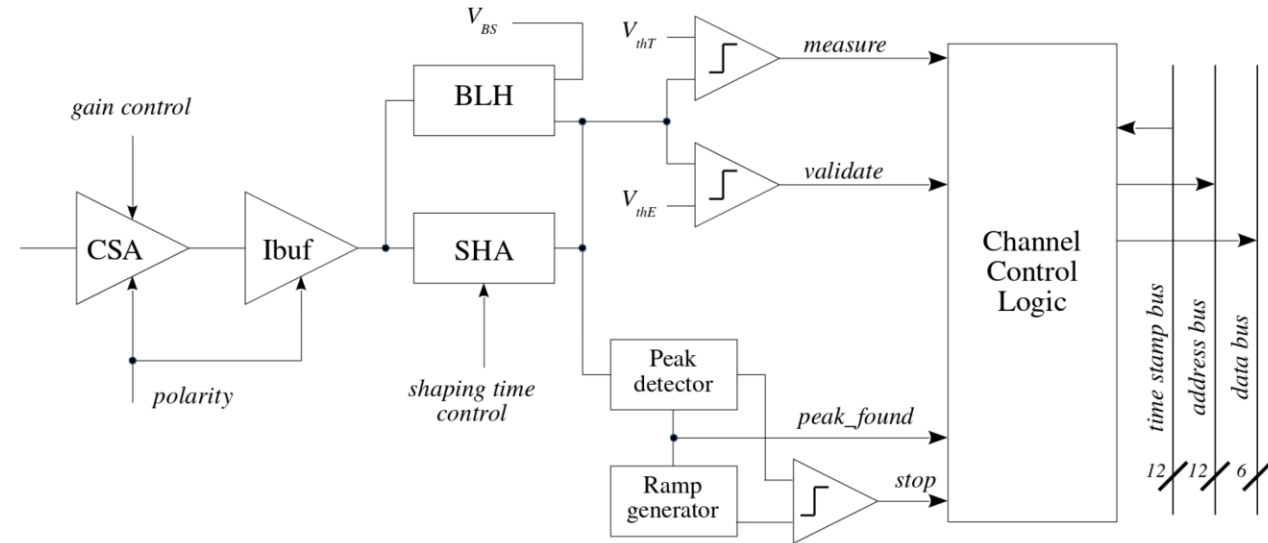
- Four gains : 2,6,9 and 12 mV/fC
- Possibility to accept inputs from both polarities

## ➤ Shaper

- 3<sup>rd</sup> order, one real and two cc poles
- Programmable peaking time : 25, 50, 150 and 250 ns

## ➤ Double threshold signal detection

- Lower threshold for time measurement, higher threshold for validation
- Peak detector signal
- Peak holder for charge measurement (via ToT)
- Linear ToT measurement



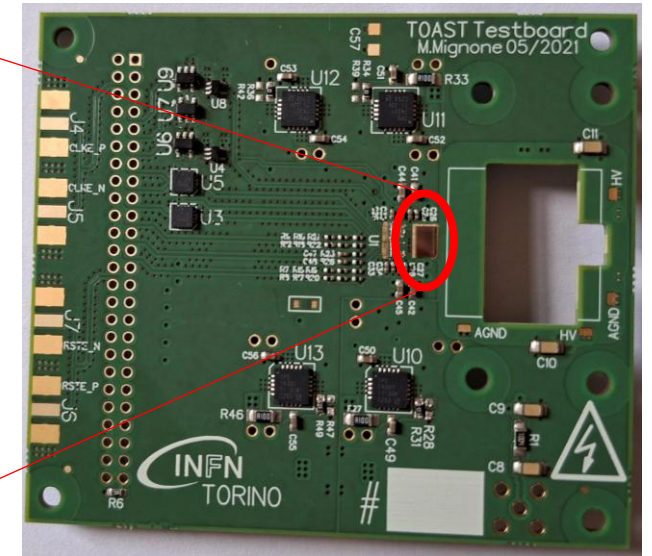
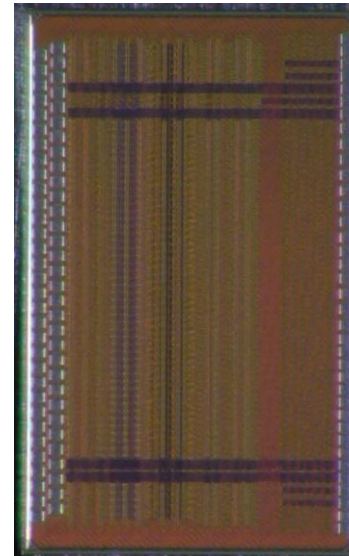
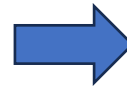
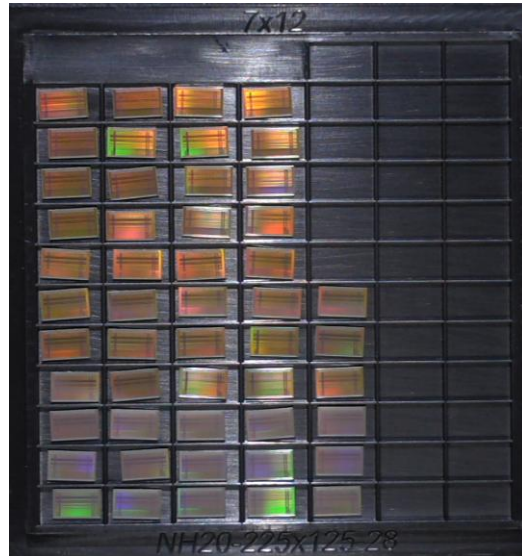
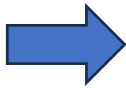
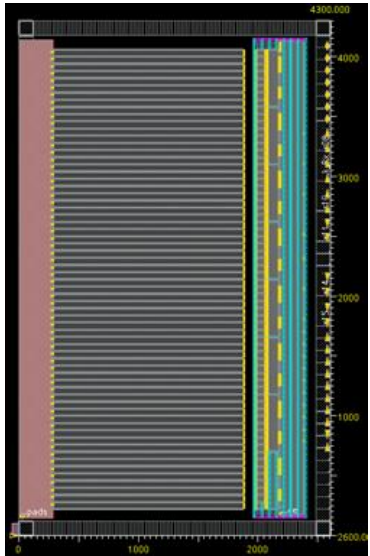
# Ongoing work

✓ The design of the ToRA\_v1 has been completed in 05.2025

✓ Delivery of the ASICs from TSMC on 11.09.25

✓ Initial inspection in Torino on 15.09.25

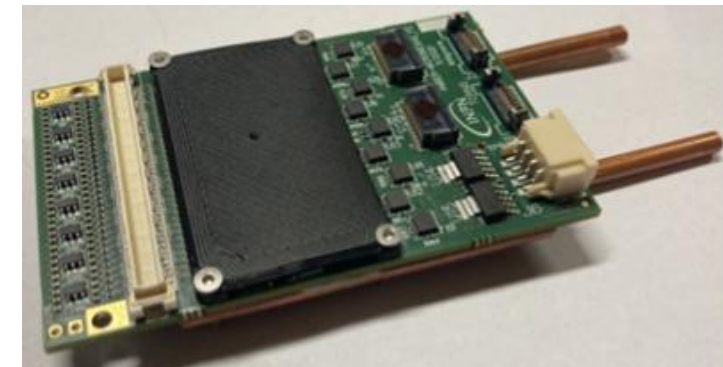
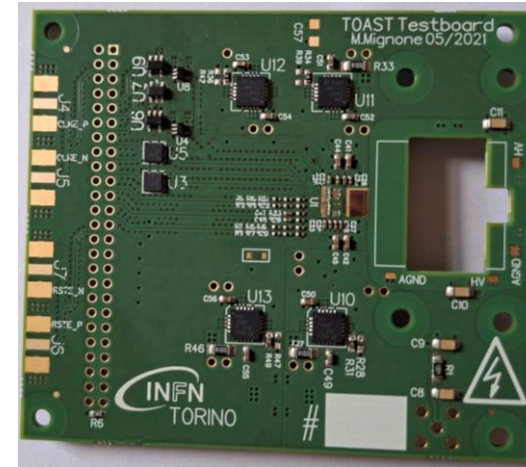
✓ Bonding of the ToRA\_v1 on a test PCB and smoke test passed on 18.09.25



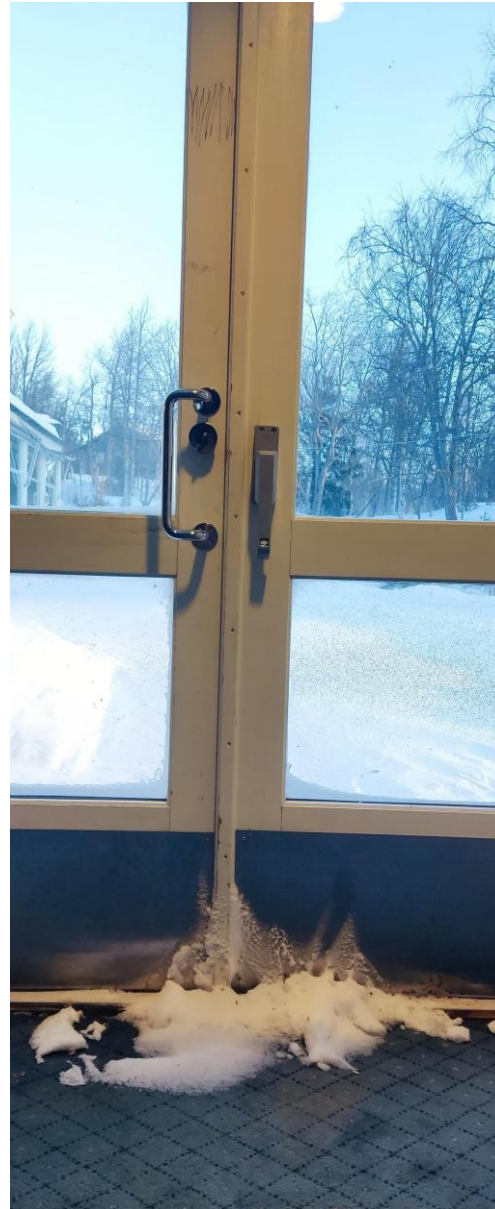


# Conclusions

- First successful test operation of the Lateral MM achieved
- Detector lab tests are ongoing
- ToRA v1 ASIC design was optimized on the base of first detector tests and the ASIC is being tested in lab conditions
- Test campaign in beam conditions is planned for 11.2025



# Spares



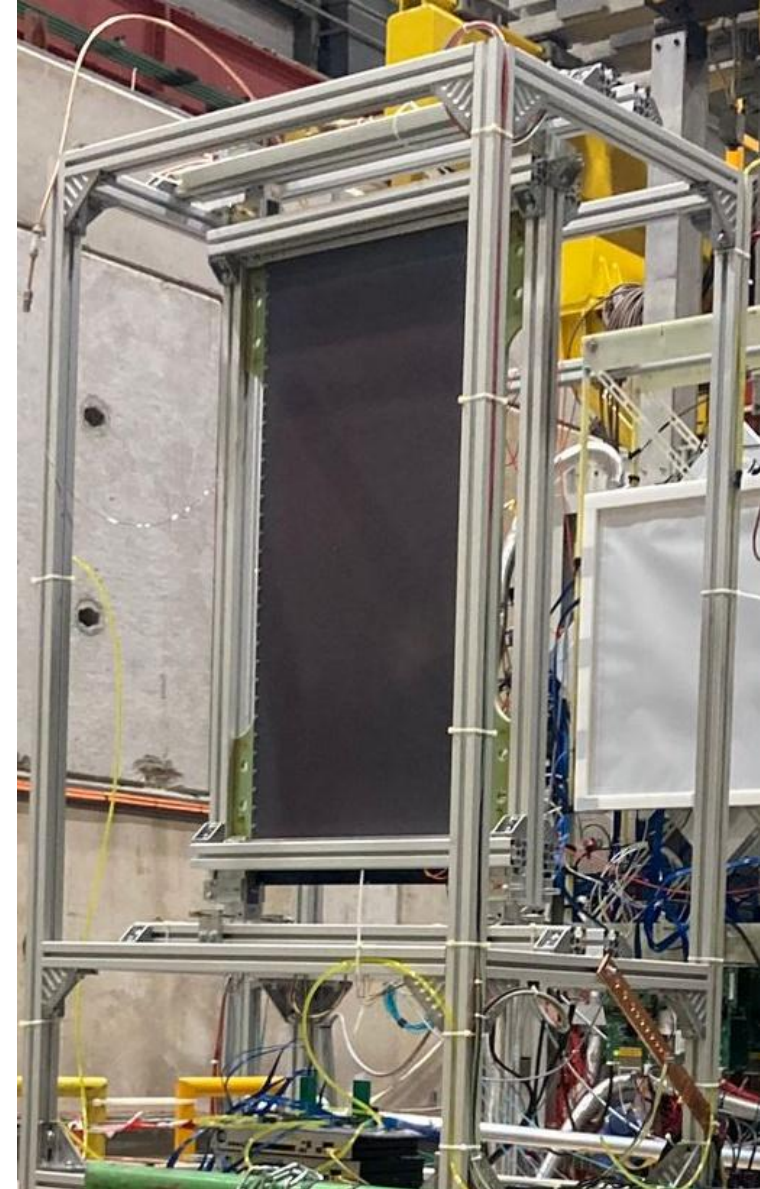
# Lateral module prototype testing

## 2024

- High Voltage stability
- Noise performance & shielding optimisation
- First data (beam/cosmics)
- Compare ArCO<sub>2</sub> (93/7) and ArCO<sub>2</sub>Iso(93/5/2)

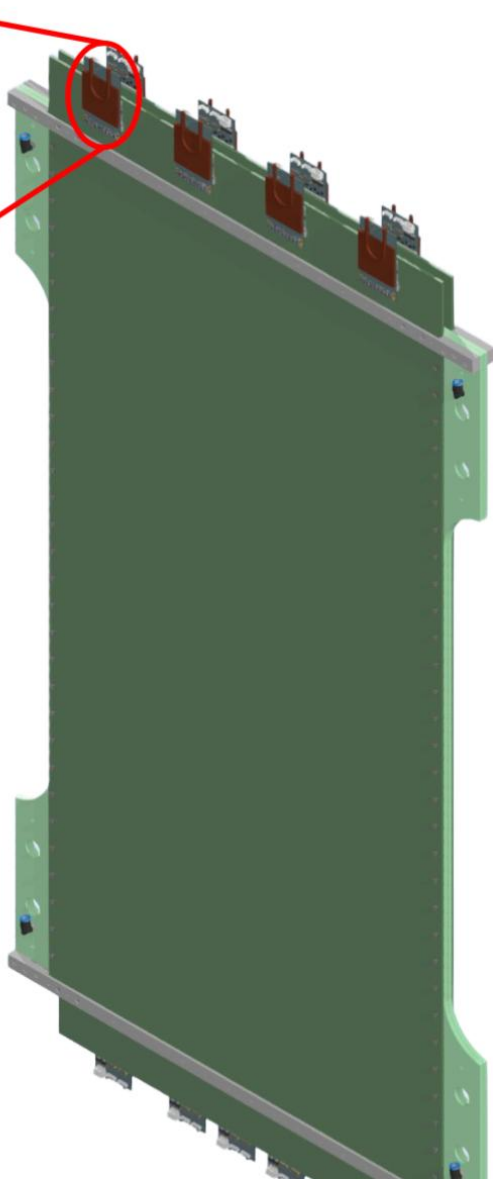
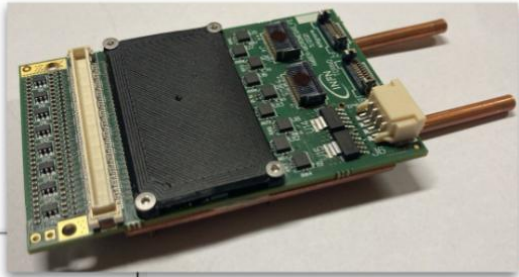
## 2025

- We will have our parasitic setup in the AMBER spectrometer for the whole beam period
- We need to achieve a stable operation/understand the problems before starting the layout of the Central module
- First test with the ToRA ASIC



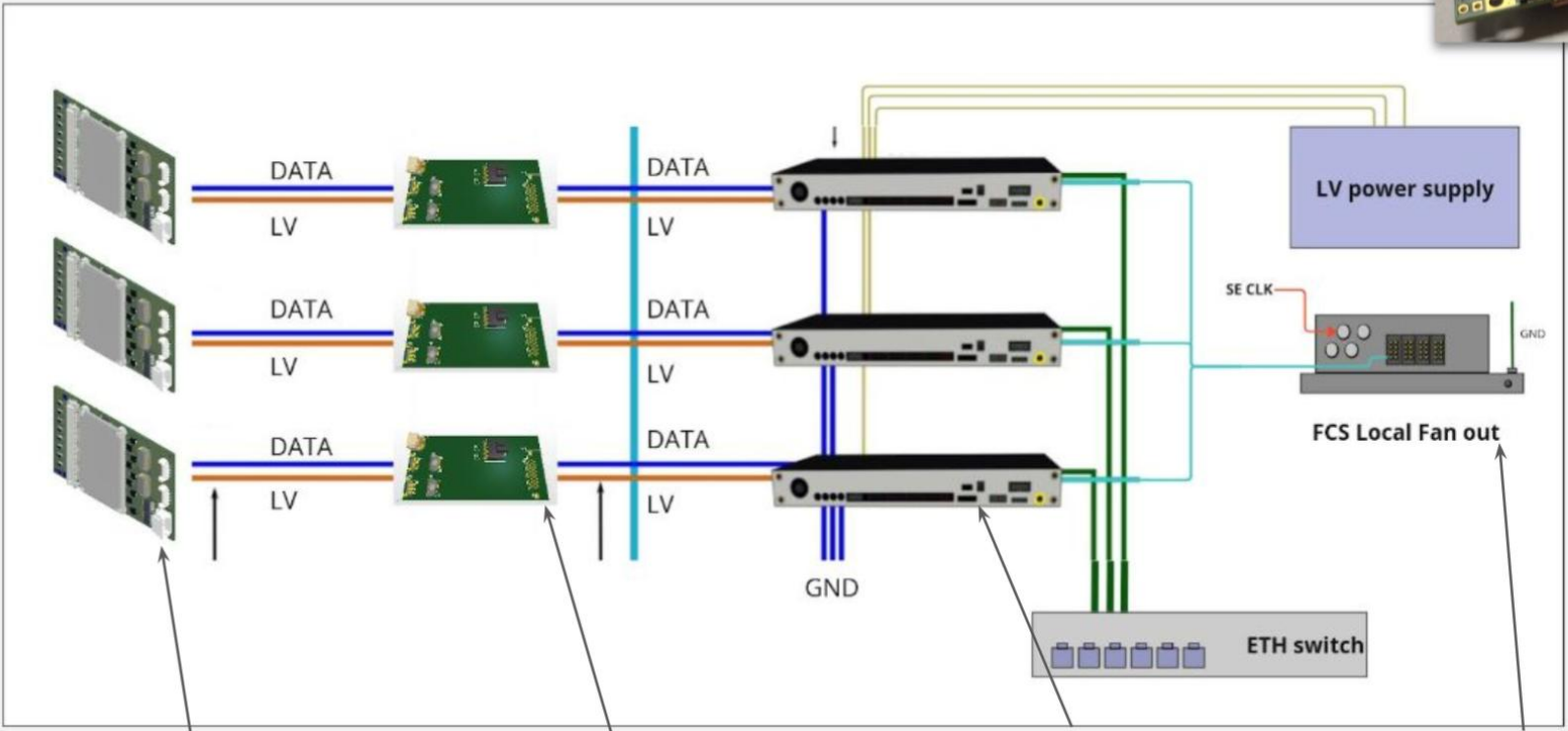


*AMBER TIGER-based readout chain:*



**6 TIGER-febs available:**

- 768/1280 UV
- 512/512 X+  
256/1280 UV connected (from shorter strips)



**AMBER-micromegas\_FE**  
designed at INFN To

TIGER-based front-end board

**Data and Low Voltage Patch Card - DLVPC**  
designed at JINR

adapter for data and LV

**GEMROC modules**  
designed at INFN Fe

Configuration and control  
signal distribution  
Data concentration

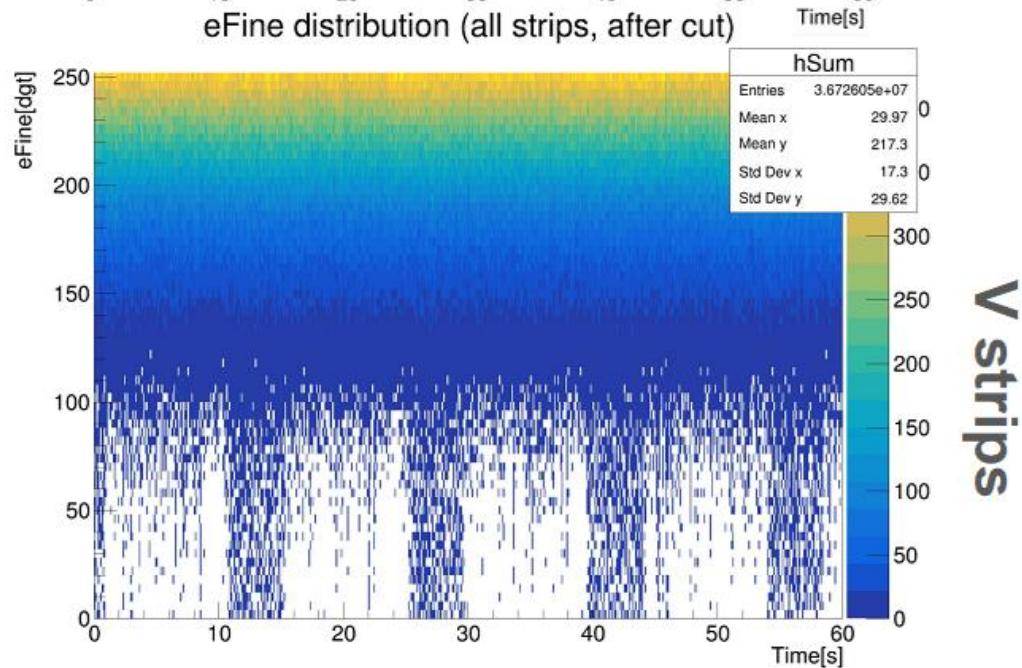
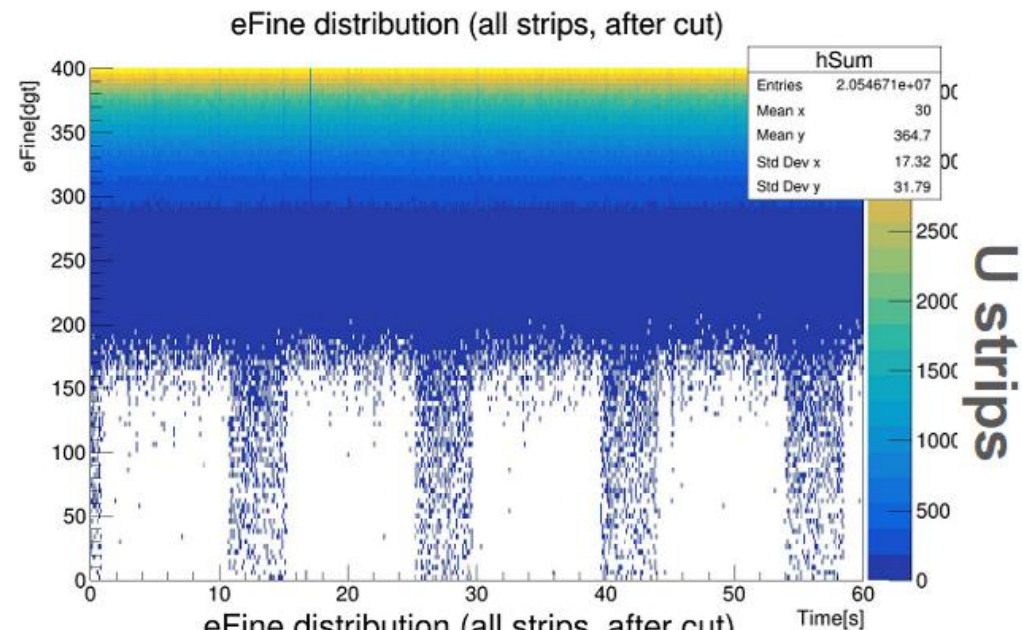
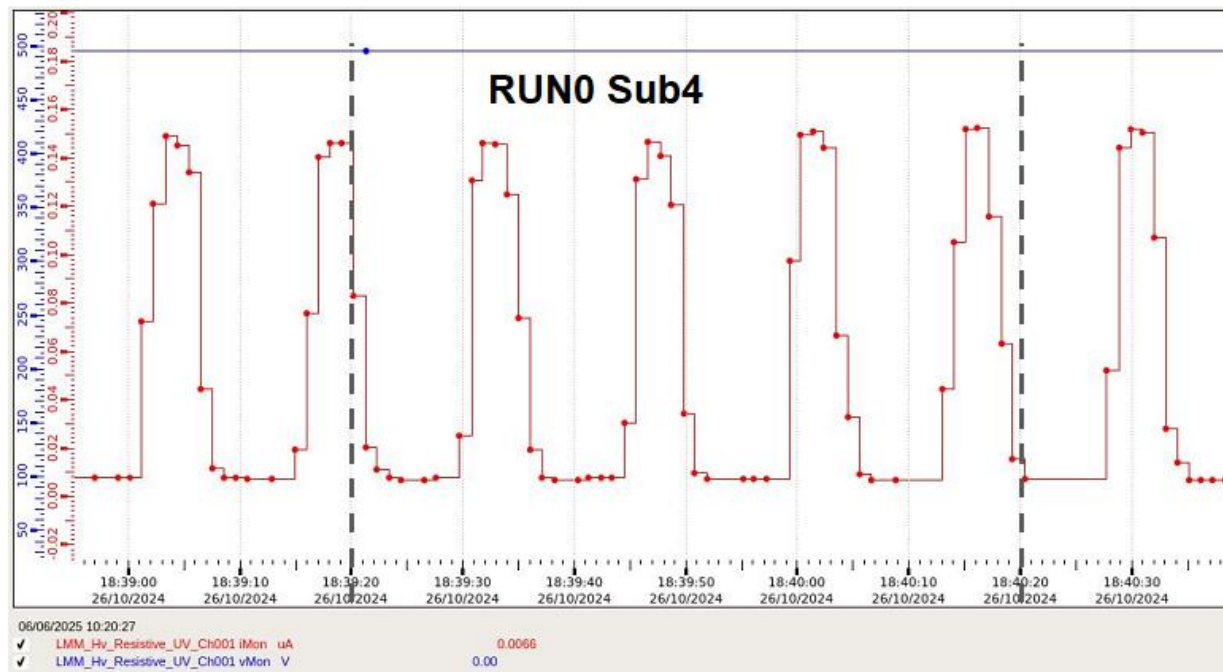
**Local FAN OUT**  
designed at INFN Fe

Trigger and clock  
distribution



# Analysis tools: charge distribution

	HV set	450V	475V	480V	490V	493V	495V
GAS mixture	Ar-CO2 93/7	RUN0 Sub0	RUN 0 Sub1	RUN0 Sub2	RUN0 Sub3	RUN1 Sub0	<b>RUN0 Sub4</b>
	Ar-CO2-iC 4H10 93/5/2		RUN4 Sub0	RUN5 Sub0	RUN2 Sub0	RUN3 Sub0	



# Main ideas

## Design in 2 steps based on feature set

- As simple as needed
- Based on existing design
- Tuned to limited use cases
- Trigger less

V1 (2024)	V2 (2025)
Limited flexibility	Implement MPGD+Wire
Power may not be optimised	Power tuning (moderate)
Mostly full backend	Inter channel commutation
Complete single channel structure	Time resolution???

# ToRA 2 step design plans

v1(2025-2026)

v2 (2026-2028)

- Base version aimed at MM (GEM) & STRAW/MWPCs
- Would be sufficient for the AMBER environment
- 4 Gains
- 4 shaping times
- Trigger less
- 1 or 2 revisions depending on performance & testing

- Actions on the inter-channel analog architecture
- Minor tuning of the channels & Backend

We have a pipeline for 2 submissions that could be (v1\_a,v1\_b) or (v1\_a,v2\_a) depending on the v1\_a performance

# V1, Back-end & data link

- Data output in 32 bits or 64 bits words over 200 Mb/s serial links
- It can be configured to use 1 or 2 links
- Frame length is of 20.48  $\mu$ s at 200 MHz
- Data within a frame are packed within a frame header and a frame trailer
- Frame header contains chip id and frame number
- Frame trailers contains the number of valid samples and CRC

Packet type	Header <i>2 bit</i>	Data <i>30 bits</i>			
Data word 0	10	Region[2:0]	Channel[2:0]	Le[11:0]	Te[11:0]
Data word 1	11	Region[2:0]	Channel[2:0]	Pk[11:0]	ToT[11:0]
Header	01	01	<i>Reserved[12:0]</i>	ChipId[6:0]	FrameN[7:0]
Trailer	01	10	DataCnt[11:0]		CRC[15:0]
Sync	00	00	1100 1100 1100	1100 1100 1100	1111

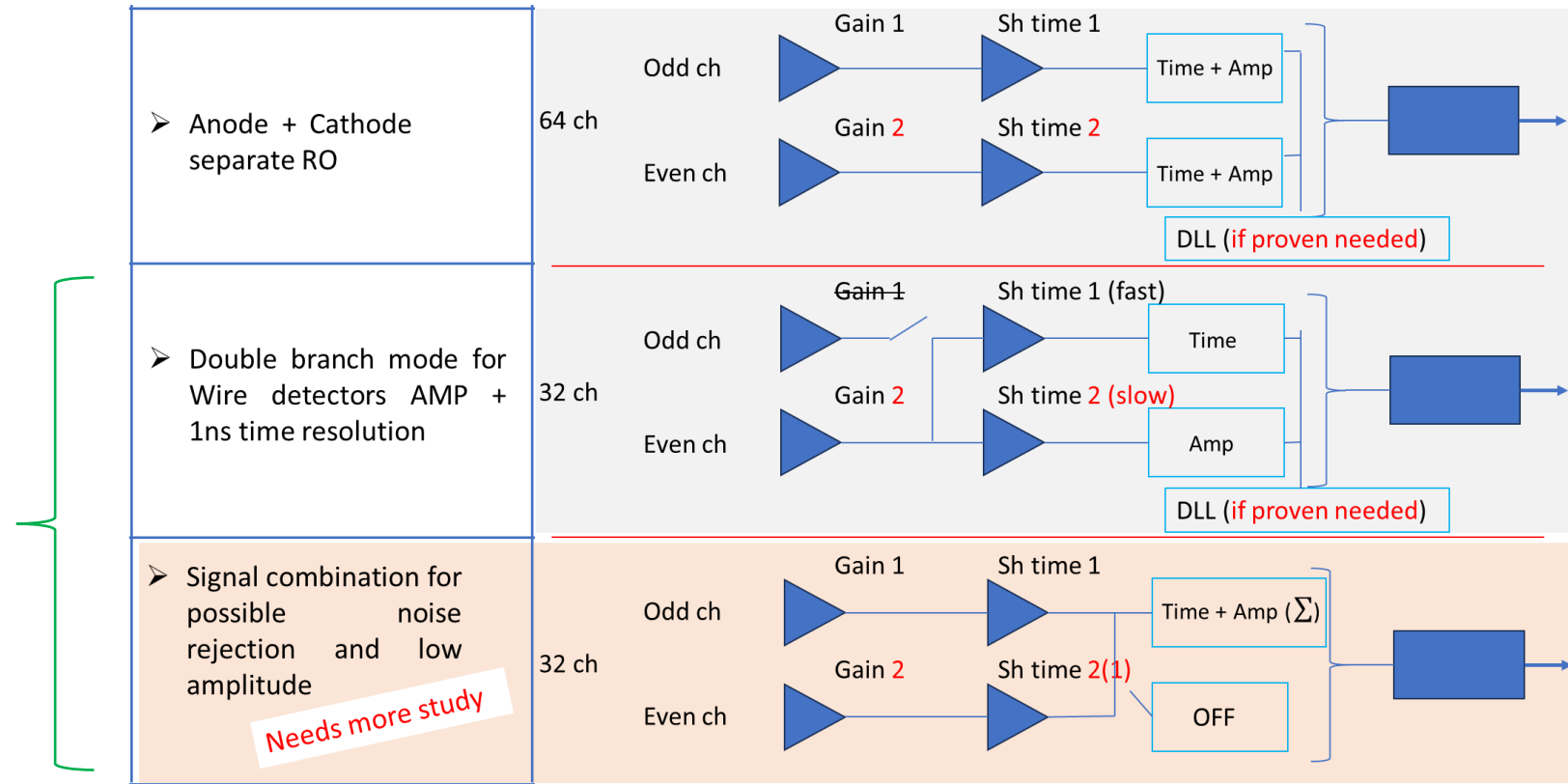


# V2 (2026-2028)

❖ Odd/even channel individual configuration

❖ Odd/even channels interconnections

❑ If better time resolution is needed



- ↳
- Channel or region-level 8-tap delay line
  - Delay controlled by a global DLL
  - Time resolution 180 ps r.m.s.